

MAYA-W2 series

Host-based multiradio modules with Wi-Fi 6, Bluetooth 5.3, and IEEE 802.15.4

Data sheet



Abstract

Targeted towards system integrators and design engineers, this technical data sheet includes the functional description, pin definition, specifications, country approval status, handling instructions, and ordering information for MAYA-W2 short-range radio modules.

This range of ultra-compact, cost-efficient, host-based, short range multiradio modules support tri-radio Wi-Fi 6, Bluetooth 5.3 (in development), and IEEE 802.15.4 connectivity. The modules are designed for a wide range of industrial applications and are supplied with or without on-board antenna. Integrated with a MAC/Baseband processor and RF front end components, this module series connects to a host processor through various interfaces, including SDIO for Wi-Fi, High-Speed UART for Bluetooth, and SPI for 802.15.4.

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Mass production / End of life	Production information	Document contains the final product specification.

This document applies to the following products:

Product name	Type number	Product status
MAYA-W260	MAYA-W260-00B-00	Initial production
MAYA-W261	MAYA-W261-00B-00	Initial production
MAYA-W266	MAYA-W266-00B-00	Initial production
MAYA-W271	MAYA-W271-00B-00	Initial production
MAYA-W276	MAYA-W276-00B-00	Initial production
MAYA-W276	MAYA-W276-00C-00	In development

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1 Functional description

1.1 Overview

Comprising ultra-compact, multiradio modules with Bluetooth 5.3, Wi-Fi 6, and IEEE 802.15.4 connectivity, the MAYA-W2 series supports IEEE 802.11a/b/g/n/ac/ax standards and delivers a data throughput of up to 480 Mbit/s (PHY data rate up to 600 Mbit/s) with dual band 2.4 / 5 GHz Wi-Fi and channel bandwidths up to 80 MHz. The modules can work as a station with different types of access-points, as a simple access-point in P2P communication, or can otherwise operate in any combination of these modes.

MAYA-W2 supports both Bluetooth BR/EDR and Bluetooth Low Energy 5.3, including long-range PHY and isochronous channels for LE audio. The MAYA-W271 and MAYA-W276 variants also include an 802.15.4 subsystem that supports the Thread mesh network.

MAYA-W2 supports an optional LTE filter and is available with or without an antenna, including variants with U.FL connectors, antenna pins, or an on-board antenna. MAYA-W2 modules come with RF calibration and MAC addresses available in the integrated OTP memory.

The modules are developed for reliable, high-demanding, industrial devices and applications that demand high performance.

Radio type approvals for Europe (RED), Great Britain (UKCA), the United States (FCC), Canada (ISED) and Japan (Giteki) are planned, and other country certifications (China, Australia, Taiwan, Brazil) can be provided on request.

1.2 Product features

Radio features	Description
Chipset	MAYA-W26x: NXP IW611 MAYA-W27x: NXP IW612
Wi-Fi Standards	Wi-Fi 6 IEEE 802.11a/b/g/n/ac/ax
Wi-Fi frequency bands	2.4 GHz, channel 1-13 5 GHz, channel 36-177
Bluetooth	Bluetooth 5.3 specification support, BR/EDR, Low Energy
802.15.4	IEEE 802.15.4-2020 compliant; supports Thread in 2.4 GHz band (MAYA-W271 and -W276)
Antenna configurations	Dual antenna for simultaneous Wi-Fi and Bluetooth/802.15.4 operation (MAYA-W260, -W261, and -W271) Single embedded antenna or antenna pin for shared 2.4 GHz Wi-Fi and Bluetooth/802.15.4 operation (MAYA-W266 and -W276)
Software features	
Security	WPA3, WPA2, and WPA mixed mode
RF calibration and MAC addresses	Available in on-board OTP memory
Wi-Fi operational modes	Station, Access-Point, Wi-Fi direct, or combination of these
Driver support	Free drivers for Linux and Android. RTOS (with certain types of NXP MCUs)
Interfaces	
Wi-Fi	SDIO 3.0 (4-bit, up to 208 MHz clock)
Bluetooth	4-wire high-speed UART, HCI transport layer PCM/I2S for audio
802.15.4	SPI (up to 10 MHz clock)
Other	GPIOs

Radio features	Description
Package	
Dimensions	10.4 x 14.3 x 2.0 mm
Mounting	Soldering, 86 pins (LGA)
Environmental data, quality, and reliability	
Operating temperature	-40 °C to +85 °C (Professional Grade), 0 °C to +70 °C (Standard Grade)
Moisture Sensitivity Level (MSL)	4
RoHS and REACH compliance	Yes
Electrical data	
RF power supply	3.0–3.6 VDC, 1.8 VDC
I/O power supply	3.3 VDC or 1.8 VDC
Certifications and approvals	
Type approvals	Europe (RED), US (FCC), Canada (ISED), Planned: Japan (Giteki); Other country certifications (China, Taiwan, Brazil) can be provided on request
Bluetooth qualification	v5.3 (Bluetooth BR/EDR and Bluetooth low energy)
Support Products	
EVK-MAYA-W276	Evaluation kit for MAYA-W276, -W266
EVK-MAYA-W271	Evaluation kit for MAYA-W271, -W261, -W260

Table 1: MAYA-W2 series product features

 For information about the supported product variants of MAYA-W260, MAYA-W261, MAYA-W266, MAYA-W271, and MAYA-W276 see [Ordering information](#).

1.3 Block diagram

Figure 1 shows the block diagram of the single antenna variants in the MAYA-W2 series. MAYA-W266 and MAYA-W276 support a single RF pin and optional antenna feed to the on-board antenna.

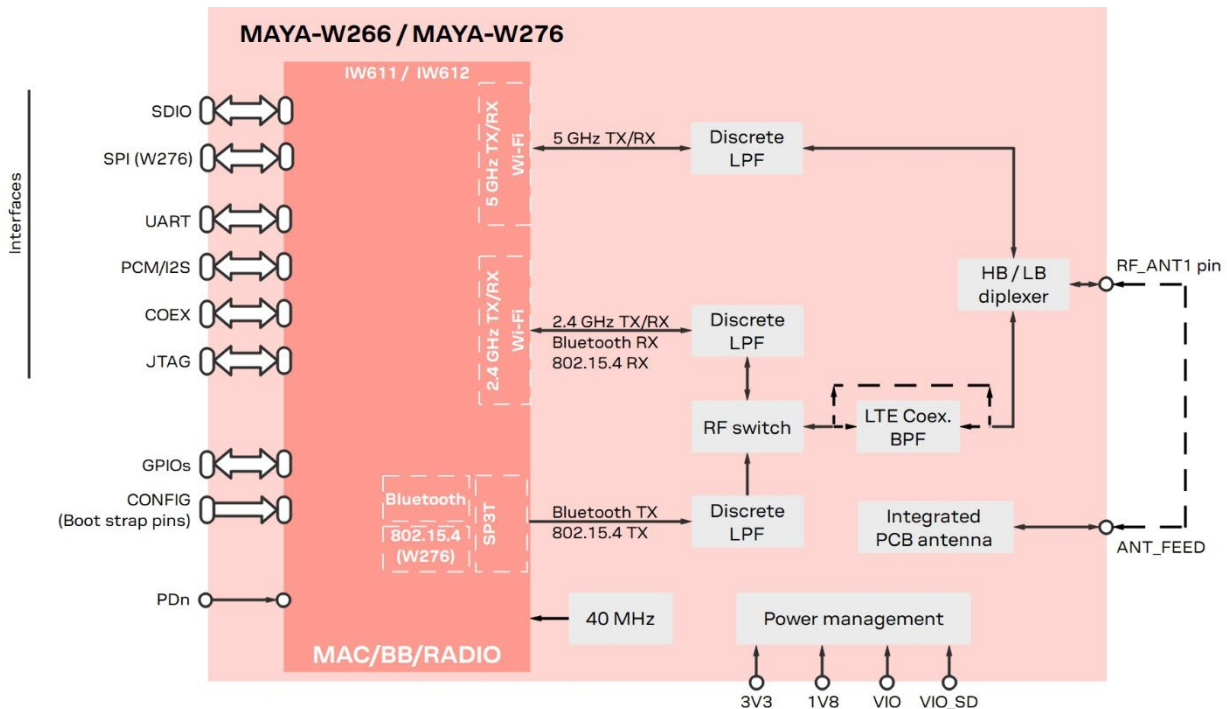


Figure 1: MAYA-W266 and MAYA-W276 block diagram

Figure 2 shows the block diagram of the dual antenna variants of MAYA-W2 series:

- MAYA-W261 supports one Wi-Fi RF pin and one Bluetooth RF pin
- MAYA-W260 supports one Wi-Fi RF U.FL connector and one Bluetooth RF U.FL connector
- MAYA-W271 supports one Wi-Fi RF pin and one shared Bluetooth/802.15.4 RF pin

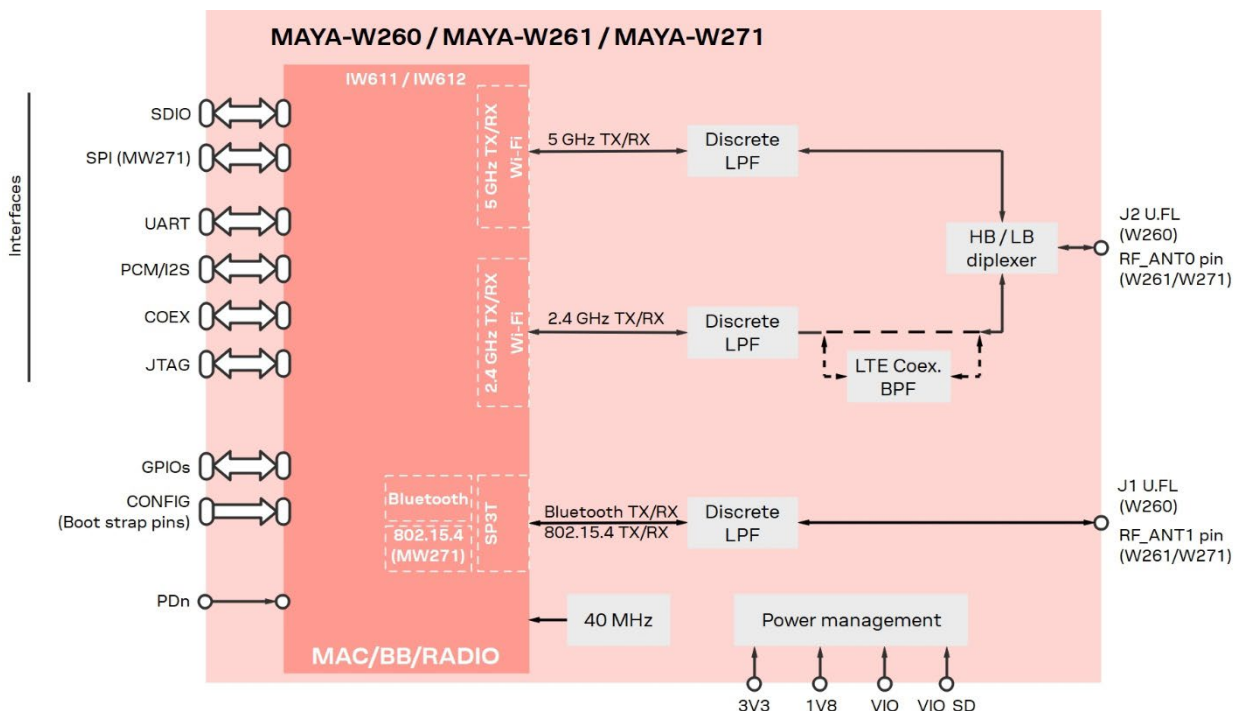


Figure 2: MAYA-W260, MAYA-W261, and MAYA-W271 block diagram

1.4 Product description

MAYA-W2 series comprises ultra-compact Wi-Fi front-end modules with a footprint of only 14.3 x 10.4 mm and is developed for reliable, high-demanding, industrial devices and applications.

Based on the NXP IW611 and IW612 chipsets, MAYA-W2 includes an integrated MAC/Baseband processor and RF front-end components.

All module variants support:

- Integrated discrete filters in the 2.4 GHz band and 5 GHz band
- Optional LTE filter for improved coexistence with LTE bands 7, 38, 40, 41

The MAYA-W2 series also offers multiple antenna solutions:

- MAYA-W260 has two U.FL connectors for connecting external antennas.
- MAYA-W261 and MAYA-W271 has two antenna pins for connecting external antennas: one for Wi-Fi and the other for Bluetooth (shared with 802.15.4 on MAYA-W271).
- MAYA-W266 and MAYA-W276 include a single RF antenna pin and optional antenna feed pin to the on-board antenna.
- Wi-Fi antenna diversity support for optimized performance with multiple external antennas.

1.5 Supported features

- Highly effective integrated antenna, antenna pin, or U. FL connectors
- Extended operating temperature range of -40 °C to +85 °C for professional grade
- Selectable 1.8 V or 3.3 V IO levels
- Internal Wi-Fi/Bluetooth/802.15.4 coexistence support

1.5.1 Wi-Fi features

- Supports Wi-Fi 6, IEEE 802.11 a/b/g/n/ac/ax
- Dual band 2.4 GHz and 5 GHz
- Single stream 802.11ax with 20, 40 and 80 MHz channel bandwidth
- Data rate up to 600 Mbit/s (MCS11)
- 802.11n short and long guard interval
- 802.11ax Extended Range, DCM and TWT
- Dynamic frequency selection (radar detection)
- Power saving features
- SDIO 3.0 device interface
- Security: WPA3, WPA2 and WPA mixed mode
- Wi-Fi Standards IEEE 802.11e/h/i/k/mc/r/u/v/w/z
- Supports simultaneous station, access point and P2P modes
- Supports up to 16 stations in AP mode (for i.MX RT MCUs 8 stations)

1.5.2 Bluetooth features

- Dual mode Bluetooth Low Energy (LE) and Bluetooth BR/EDR
- Bluetooth 5.3 specification support
- Bluetooth Class 1 and Class 2 operation
- Bluetooth LE long range (125/500 kbps) support – improving the range up to four times
- Bluetooth LE 1, 2 Mbit/s PHY
- Bluetooth LE advertising extensions for improved capacity
- Isochronous channels (ISOC) supporting Bluetooth Low Energy (LE) audio
- High-speed UART host interface with standard HCI transport layer
- I2S and PCM interface for voice applications
- Encryption (AES) support
- Bluetooth LE Broadcaster, Observer, Central, and Peripheral roles
- Bluetooth LE link layer topology (connects to 16 links)
- Bluetooth LE Privacy 1.2
- Bluetooth LE Secure Connection
- Bluetooth LE Data Length and Advertising Extension

1.5.3 802.15.4 features

- IEEE 802.15.4-2020 compliant supporting Thread in 2.4 GHz band
- Shared transmitter and antenna pin with Bluetooth
- Simultaneous receive with Wi-Fi and Bluetooth
- MAC accelerator with packet formatting, CRCs, address check, auto-acks, timers

1.6 Reserved MAC addresses

MAYA-W2 series modules have four consecutive MAC addresses that are unique for each module variant. The first three of these four addresses are configured during production.

The first address is used for the Bluetooth communication, while the second address is configured for Wi-Fi communication. The third address is extended to a 64-bit MAC address by inserting two 00-hex bytes and used for the 802.15.4 radio. The Data Matrix Code shown on the product label includes the Bluetooth MAC address. See also [Product labeling](#). The remaining MAC address is not used in the manufacturing configuration but is reserved for module usage.

MAC address	Assignment	Last two bits of MAC address	Example
Module1, address 1	Bluetooth	00	D4:CA:6E:44:00:04
Module1, address 2	Wi-Fi	01	D4:CA:6E:44:00:05
Module1, address 3	802.15.4	10	D4:CA:6E:00:00:44:00:06
Module1, address 4	(free for use)	11	D4:CA:6E:44:00:07
Module2, address 1	Bluetooth	00	D4:CA:6E:44:00:08
Module2, address 2	Wi-Fi	01	D4:CA:6E:44:00:09
Module2, address 3	802.15.4	10	D4:CA:6E:00:00:44:00:0A
Module2, address 4	(free for use)	11	D4:CA:6E:44:00:0B

Table 2: MAC address assignment

2 Interfaces

2.1 Interface configuration

Depending on the pin multiplexing and strap settings, the hardware state at power-on can differ. The state of the hardware is determined by the pin state at power-on – after the boot code finishes and before the firmware download begins.

To set a configuration bit to 0, attach a 51 kΩ resistor from the pin to ground. No external circuitry is required to set a configuration bit to 1.

MAYA-W2 supports two configuration pins, CONFIG[0] and CONFIG[1], for selecting the host interface configuration, as shown in [Table 3](#). Additional configuration pins are required to set configuration parameters following a hardware reset, as described in [Table 4](#). Configuration pins revert to normal function after boot-up.

CONFIG[1:0]	Wi-Fi	Bluetooth	802.15.4
11	SDIO	UART	SPI
Others	Reserved	Reserved	Reserved

Table 3: Firmware boot options

Configuration bits	Pin name	Configuration function
CON[7]	RF_CNTL4	Reserved. Set to 1 or do not connect.
CON[5]	RF_CNTL3	Reserved. Set to 1 or do not connect.
CON[1:0]	CONFIG[1:0]	Host configuration options. Selects the host interface used for Wi-Fi and Bluetooth. 11 = (default). See Table 3 .

Table 4: Configuration pins

2.2 Host interfaces

MAYA-W2 supports the following high-speed host interfaces:

- SDIO 3.0 device interface for Wi-Fi
- UART interface for Bluetooth
- SPI interface for 802.15.4 radio (MAYA-W271 and -W276)

The host interfaces for Wi-Fi and Bluetooth are selected using the configuration pins described in [Table 3](#).

2.2.1 SDIO interface

MAYA-W2 supports an SDIO device interface that conforms to the industry standard SDIO 3.0 specification, including default speed (25 MHz), high-speed (50 MHz), SDR12/25/50/104 (12/25/50/104 MB/s), and DDR50 (50 MB/s) modes. The interface supports 1-bit and 4-bit SDIO transfer modes at the full clock range up to 208 MHz for SDR104. All mandatory SDIO commands are supported.

In 4-bit SDIO mode, data is transferred on all four data pins (**SD_DAT[3:0]**). The interrupt pin is not available for exclusive use as it is utilized as a data transfer line. If the interrupt function is required, special timing is required to provide interrupts. The 4-bit SDIO mode provides the highest data transfer possible with speeds up to 104 MB/s in SDR104 mode.

The pull-up resistors required for the SD interface on **SD_CMD**, **SD_DAT [3:0]** must be provided by the host, the value of resistors should be between 10–100 kΩ.

Low value series termination resistors can be required to help with signal integrity. The SDIO signals levels are selectable according to the **VIO_SD** 1.8/3.3 voltage levels (depending on SDIO mode selection). See [Power supply interfaces](#).

[Table 5](#) describes the required pins for the SDIO interface.

Pin name	I/O type	1-bit mode	4-bit mode
SD_DAT[0]	I/O	DATA: Data line	Data line 0
SD_DAT[1]	I/O	IRQ: Interrupt	Data line 1
SD_DAT[2]	I/O	RW: Read Wait	Data line 2
SD_DAT[3]	I/O	N/C: Not used	Data line 3
SD_CMD	I/O	Command line	Command line
SD_CLK	I	Clock input	Clock input

Table 5: SDIO interface pin description

2.2.1.1 Default speed and high-speed modes (3.3 V)

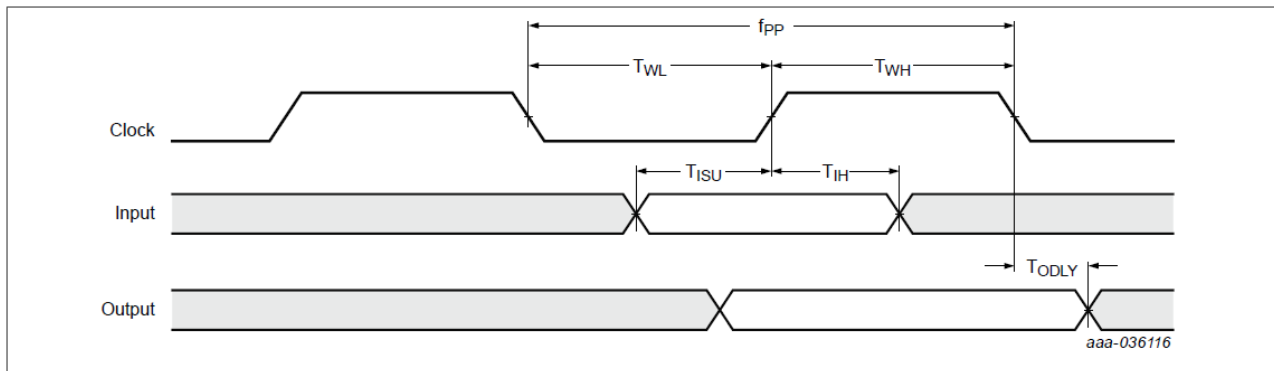


Figure 3: SDIO protocol timing diagram - default speed mode

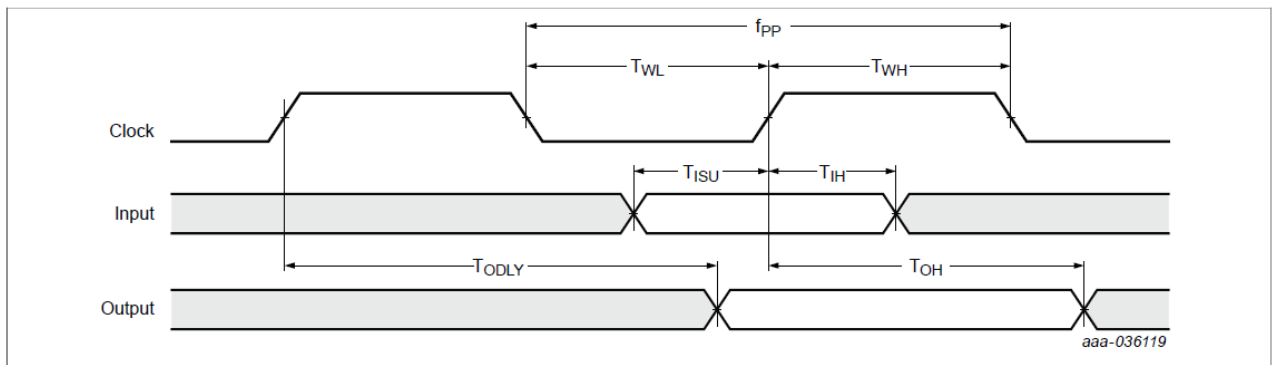


Figure 4: SDIO protocol timing diagram – high speed mode

[Table 6](#) describes the SDIO timing data for the default and high-speed modes with the SDIO clock running at 25 MHz or 50 MHz.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{pp}	Clock frequency	Default speed	0	-	25	MHz
		High speed	0	-	50	MHz
T_{WL}	Clock low time	Default speed	10	-	-	ns
		High speed	7	-	-	ns
T_{WH}	Clock high time	Default speed	10	-	-	ns
		High speed	7	-	-	ns
T_{ISU}	Input setup time	Default speed	5	-	-	ns

Symbol	Parameter	Condition	Min	Typ	Max	Unit
T_{IH}	Input hold time	High speed	6	-	-	ns
		Default speed	5	-	-	ns
		High speed	2	-	-	ns
T_{ODLY}	Output Delay Time	Default speed	-	-	14	ns
		High speed	-	-	14	ns
T_{OH}	$CL \leq 40$ pF (1 card)	Default speed	2.5	-	-	ns
		High speed	-	-	-	ns

Table 6: SDIO timing data – default and high-speed modes

2.2.1.2 SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8 V)

Table 7 describes the SDIO timing data for the SDR12/25/50 modes with the SDIO clock running at up to 100 MHz. The **VIO_SD** power pin must be supplied at 1.8 V.

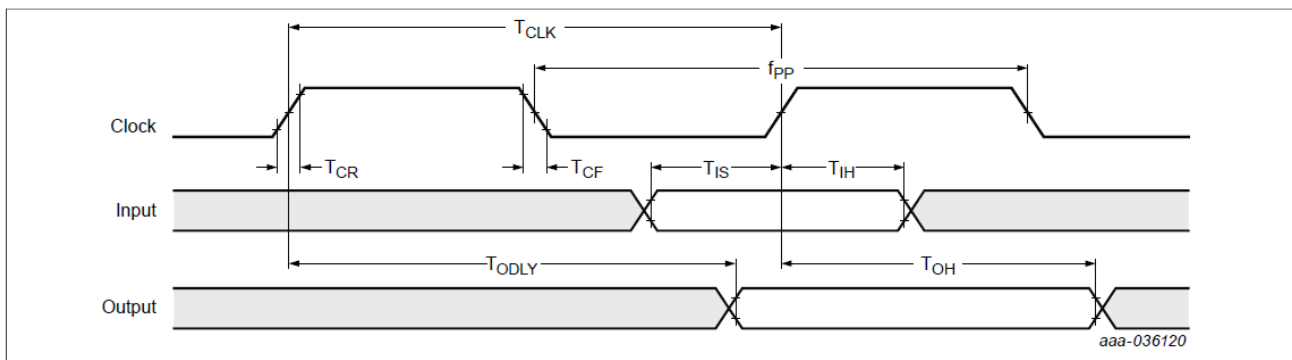


Figure 5: SDIO protocol timing diagram – SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8 V)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{pp}	Clock frequency	SDR 12	0	-	25	MHz
		SDR 25	0	-	50	
		SDR 50	0	-	100	
T_{IS}	Input setup time	SDR 12	5	-	-	ns
		SDR 25	6	-	-	
		SDR 50	3	-	-	
T_{IH}	Input hold time	SDR 12	5	-	-	ns
		SDR 25	2	-	-	
		SDR 50	0.8	-	-	
T_{CLK}	Clock time	SDR 12	40	-	40	ns
		SDR 25	10	-	20	
		SDR 50	10	-	10	
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 2$ ns (max) at 100 MHz $C_{CARD} = 10$ pF	SDR 12	-	-	$0.2 \cdot T_{CLK}$	ns
		SDR 25	-	-	$0.2 \cdot T_{CLK}$	ns
		SDR 50	-	-	$0.2 \cdot T_{CLK}$	ns
T_{ODLY}	Output delay time $C_L \leq 30$ pF	SDR 12	-	-	7.5	ns
		SDR 25	-	-	14	ns
		SDR 50	-	-	14	ns
T_{OH}	Output hold time $C_L = 15$ pF	SDR 12	1.5	-	-	ns
		SDR 25	1.5	-	-	ns
		SDR 50	1.5	-	-	ns

Table 7: SDIO timing data – SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8 V)

2.2.1.3 DDR50 mode (50 MHz) (1.8 V)

Table 8 describes the SDIO timing data for the DDR50 mode with the SDIO clock running at 50 MHz. The **VIO_{SD}** power pin must be supplied at 1.8 V.

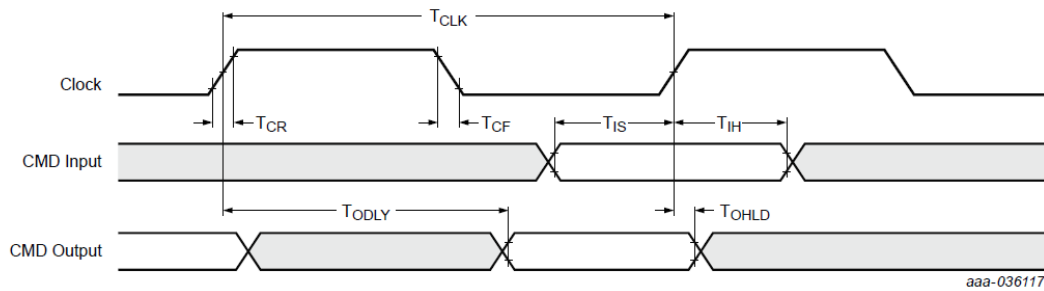


Figure 6: SDIO CMD timing diagram – DDR50 mode (50 MHz)

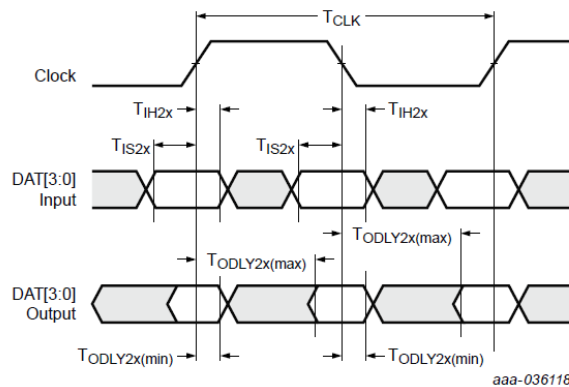


Figure 7: SDIO DAT[3:0] timing diagram – DDR50 mode

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Clock						
T_{CLK}	Clock time 50 MHz (max) between rising edges	DDR 50	20	–	–	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 4.00$ ns (max) at 50 MHz $C_{CARD} = 10$ pF	DDR 50	–	–	$0.2 \cdot T_{CLK}$	ns
Clock duty	–	DDR 50	45	–	55	%
CMD input (with reference to rising clock edge)						
T_{IS}	Input setup time $C_{CARD} = 10$ pF (1 card)	DDR 50	6	–	–	ns
T_{IH}	Input hold time $C_{CARD} = 10$ pF (1 card)	DDR 50	0.8	–	–	ns
CMD output (referenced to clock rising edge)						
T_{ODLY}	Output delay time during data transfer mode $C_L \leq 30$ pF (1 card)	DDR 50	–	–	13.7	ns
T_{OHLD}	Output hold $C_L \geq 15$ pF (1 card)	DDR 50	1.5	–	–	ns
DAT[3:0] Input (referenced to clock rising and falling edges)						
T_{IS2x}	Input setup time $C_{CARD} \leq 10$ pF (1 card)	DDR 50	3	–	–	ns
T_{IH2x}	Input hold time $C_{CARD} \leq 10$ pF (1 card)	DDR 50	0.8	–	–	ns
DAT[3:0] Output (referenced to clock rising and falling edges)						
T_{ODLY2x}	Output delay time during data transfer mode	DDR 50	–	–	7.0	ns

Symbol	Parameter	Condition	Min	Typ	Max	Unit
(max)	$C_L \leq 25 \text{ pF}$ (1 card)					
T_{ODLY2x}	Output hold time	DDR 50	1.5	–	–	ns
(min)	$C_L \geq 15 \text{ pF}$ (1 card)					

Table 8: SDIO timing data – DDR50 mode (50 MHz)

2.2.1.4 SDR104 mode (208 MHz) (1.8 V)

Table 9 describes the SDIO timing data for the SDR104 mode with SDIO clock running at 208 MHz. The **VIO_SD** power pin must be supplied at 1.8 V.

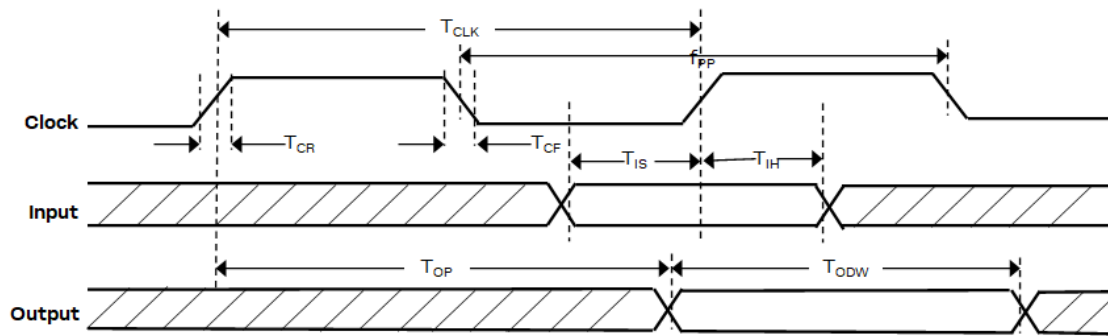


Figure 8: SDIO DAT[3:0] timing diagram – SDR104 mode

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{PP}	Clock frequency	SDR104	0	–	208	MHz
T_{IS}	Input setup time	SDR104	1.4	–	–	ns
T_{IH}	Input hold time	SDR104	0.8	–	–	ns
T_{CLK}	Clock time	SDR104	4.8	–	–	ns
T_{CR}, T_{CF}	Rise time, fall time $T_{CR}, T_{CF} < 0.96 \text{ ns}$ (max) at 208 MHz $C_{CARD} = 10 \text{ pF}$	SDR104	--	--	$0.2 * T_{CLK}$	ns
T_{OP}	Card output phase	SDR104	0	–	2	ns
T_{ODW}	Output timing of variable data window	SDR104	2.88	–	–	ns

Table 9: SDIO timing data – SDR104 mode (208MHz)

2.2.1.5 SDIO internal pull-up and pull-down specifications

Parameter	Condition	Min	Typ	Max	Unit
Internal nominal pull-up/pull-down resistance		70	100	140	kΩ

Table 10: SDIO internal pull-up and pull-down specifications

2.2.2 UART interface

MAYA-W2 supports a high-speed UART host interface for Bluetooth operation. The baud rate is adjustable from 1200 bps to 3.0 Mbit/s and the default baud rate after reset is 115.2 Kbps. The acceptable deviation from the UART Rx target baud rate is $\pm 3\%$. The UART supports RX/TX pins and mandatory RTS/CTS flow control signals. [Table 11](#) describes the module pins for the UART interface.

Pin name	I/O type	Description	GPIO pin multiplexing
UART_CTS	I	Active low clear-to-send input signal	GPIO[8]
UART_TX	O	UART serial output signal	GPIO[11]
UART_RX	I	UART serial input signal	GPIO[10]
UART_RTS	O	Active low request-to-send signal	GPIO[9]

Table 11: Bluetooth UART interface description

2.2.3 SPI interface

MAYA-W271 and MAYA-W276 support an SPI host interface for the 802.15.4 radio with a maximum clock speed of 10 MHz. The pins are shared with the external PTA coexistence interface. [Table 12](#) describes the module pins for the SPI interface.

Pin name	I/O type	Description	GPIO pin multiplexing
SPI_FRM	I	SPI frame input signal	GPIO[13]
SPI_CLK	I	SPI clock input signal	GPIO[12]
SPI_RX	I	SPI receive input signal	GPIO[14]
SPI_TX	O	SPI transmit output signal	GPIO[15]

Table 12: 802.15.4 SPI interface description

2.3 Antenna interfaces

The MAYA-W2 series supports either an on-board antenna or single antenna pin – configured externally by either a 0 Ω jumper (MAYA-266 and MAYA-W276), two external antennas connected through the antenna pins (MAYA-W261, MAYA-W271), or through the on-module U.FL connectors (MAYA-W260).

To prevent mutual interference and improve coexistence performance with LTE bands, MAYA-W2 supports an optionally integrated, high-performance 2.4 GHz SAW LTE band pass filter.

[Table 13](#) shows the available antenna interfaces on MAYA-W2 series modules.

Product name	Antenna interface	Description
MAYA-W260	RF_ANT0	U.FL connector (J2) for external 2.4/5 GHz Wi-Fi antenna
	RF_ANT1	U.FL connector (J1) for external Bluetooth antenna
MAYA-W261	RF_ANT0	Antenna pin for external 2.4/5 GHz Wi-Fi antenna
	RF_ANT1	Antenna pin for external Bluetooth antenna
MAYA-W266	RF_ANT1	Antenna pin for external 2.4/5 GHz Wi-Fi and Bluetooth antenna. Bluetooth and 2.4 GHz Wi-Fi are time-shared.
	ANT_FEED	External antenna feed pin from RF_ANT1 for embedded PCB antenna.
MAYA-W271	RF_ANT0	Antenna pin for external 2.4/5 GHz Wi-Fi antenna
	RF_ANT1	Antenna pin for external Bluetooth/802.15.4 antenna
MAYA-W276	RF_ANT1	Antenna pin for external 2.4/5 GHz Wi-Fi, Bluetooth and 802.15.4 antenna. Bluetooth, 802.15.4, and 2.4 GHz Wi-Fi are time-shared.
	ANT_FEED	External antenna feed pin from RF_ANT1 for embedded PCB antenna.

Table 13: MAYA-W2 antenna configurations

2.3.1 On-board antenna

MAYA-W266 and MAYA-W276 have an on-board niche (embedded) 2.4/5 GHz antenna that is specifically designed and optimized for the MAYA form factor. The module has an RF signal pin (**RF_ANT1**) and an antenna feed pin for the embedded antenna (**ANT_FEED**), so it is possible to use either an external antenna connected to **RF_ANT1**, or the embedded antenna by connecting **RF_ANT1** to the **ANT_FEED** pin.

2.3.2 External RF antenna interface

MAYA-W260, MAYA-W261, and MAYA-W271 are equipped with either dual RF pins (**RF_ANT0**, **RF_ANT1**) or U.FL connectors (**J1**, **J2**) that have a 50 Ω characteristic impedance for use with an external antenna. The antenna connectors / pins support Wi-Fi dual band on connector **J2** (**RF_ANT0**) and Bluetooth/802.15.4 on connector **J1** (**RF_ANT1**).

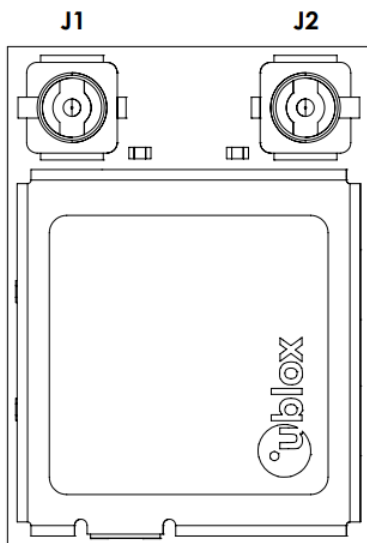


Figure 9 MAYA-W260 antenna configuration (top view)

The external antenna can be an SMD antenna (or PCB integrated antenna) mounted on the host board. An antenna connector for use with an external antenna through a coaxial cable can also be considered. The use of a cable antenna can be necessary if the module is mounted in a shielded enclosure, such as a metal box or cabinet. See the list of approved antennas [2].

All MAYA-W2 variants support a switching antenna diversity solution for Wi-Fi through RF control of an external antenna switch. The switch is controlled by the **RF_CNTL3** signal from the MAYA-W2 module. For more information about antenna switch design, see also the MAYA-W2 series system integration manual [2].

2.4 Power supply interfaces

The DC power for MAYA-W2 series modules is supplied through **3V3**, **1V8**, **VIO** and **VIO_SD** pins.

The separate **VIO** pin enables integration of MAYA-W2 in either 1.8 V or 3.3 V applications – without the need for level converters.

VIO_SD is used for digital 1.8 V/3.3 V SDIO power supply.

2.4.1 Power up sequence timing

The module has no power up-sequence requirements. The power-down (**PDn**) pin must be held low (asserted) until all external power supply rails are stable. See [Figure 10](#). T_{PU_RESET} is defined in [Table 14](#).

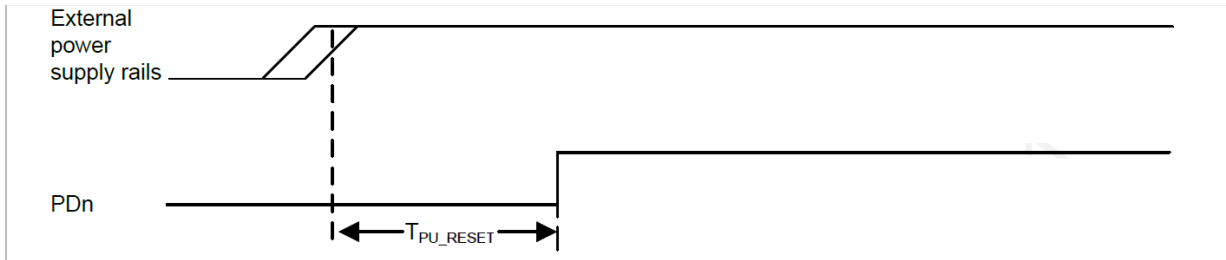


Figure 10: Power-up sequence for MAYA-W2 module

2.4.2 Power down

MAYA-W2 series modules can be put into the lowest power mode when Wi-Fi and Bluetooth are not in use. To do this, assert **PDn** low to enter power-down mode. Firmware download is required again after exiting power-down mode. If the firmware is not downloaded, the device must be kept in power-down mode to reduce leakage. Alternatively, **3V3**, **1V8**, **VIO** and **VIO_SD** can be powered off. In this case, the state of the **PDn** pin becomes irrelevant. See [Figure 11](#).

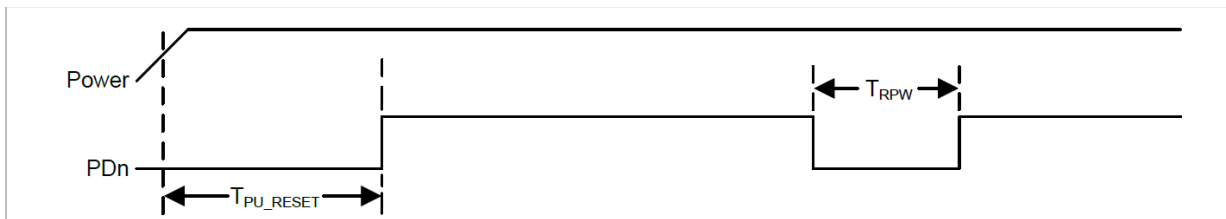


Figure 11: PDn timing

Symbol	Parameter	Condition	Min	Typ	Max	Unit
T_{PU_RESET}	Valid power to PDn deasserted	-	0	-	-	ms
T_{RPW}	PDn pulse width	-	1	-	-	us
V_{IH}	Input high voltage	-	1.4	-	4.5	V
V_{IL}	Input low voltage	-	-0.4	-	0.5	V

Table 14: PDn pin specifications

2.4.3 Reset

MAYA-W2 series is reset by asserting **PDn** low while power supplies remain active.

2.5 Wake-up and reset interfaces

A deep sleep mode in MAYA-W2 is used to reduce power consumption. [Table 15](#) shows optional out-of-band wake-up pins to wake up the radios from sleep mode. Radio-to-host, wake-up output signals can be used to wake up the host from sleep mode.

Pin name	I/O type	Description	GPIO pin muxing
WL_WAKE_HOST	O	Wi-Fi radio to host wake-up output signal	GPIO[17]
WL_DEV_WAKE	I	Wi-Fi radio wake-up input signal	GPIO[16]
BT_15.4_WAKE_HOST	O	Bluetooth/802.15.4 radio to host wake-up output signal	GPIO[19]
BT_15.4_DEV_WAKE	I	Bluetooth/802.15.4 radio wake-up input signal	GPIO[18]
SPI_INT	O	SPI interrupt output signal	GPIO[20]
SD_INT	O	Optional SDIO interrupt output signal	GPIO[21]

Table 15: Wake-up pins

Software reset pins can be used to independently reset the Wi-Fi and Bluetooth/802.15.4 radios in MAYA-W2.

Pin name	I/O Type	Description	GPIO pin muxing
WL_RST	I	Independent software reset for Wi-Fi	GPIO[1]
BT_15.4_RST	I	Independent software reset for Bluetooth. The request to reset Bluetooth will also reset the 802.15.4 radio in MAYA-W271/-W276.	GPIO[2]
RST_IND	O	Bluetooth/802.15.4 independent software reset indicator to host	GPIO[22]

Table 16: Software reset pins

2.6 GPIOs

MAYA-W2 supports up to 20 GPIO pins. On power-up and reset, the GPIO pins assume a high-impedance tristate. The UART, PCM, and JTAG interfaces can be assigned to the GPIO pins. After initialization, firmware is downloaded, and the pads are programmed in line with the functionality of the GPIOs. See also [Pin assignment](#).

For information describing what GPIOs are used for the interfaces, see [UART](#), [PCM/I2S audio interfaces](#), [PTA/WCI-2 external coexistence interfaces](#) and [JTAG](#). All other GPIOs are described in the [Pin definition](#).

2.7 PCM/I2S audio interfaces

MAYA-W2 supports PCM and I2C interfaces on the same pins with:

- PCM pins shared with I2S pins
- PCM central or peripheral mode
- PCM bit-width size of 8 bits or 16 bits
- Up to 4 PCM slots with configurable bit width and start positions
- PCM short-frame and long-frame synchronization
- I2S central and peripheral modes for I2S, MSB, and LSB audio interfaces
- Tri-state capability

The interfaces connect to linear codec devices in central or peripheral mode.

[Table 17](#) describes the chipset pins that connect directly to the PCM pins of MAYA-W2.

Pin name	I/O Type	Description	GPIO pin muxing
PCM_DOUT / I2S_DOUT	O	PCM/I2S data out	GPIO[5]
PCM_DIN / I2S_DIN	I	PCM/I2S data in	GPIO[6]
PCM_CLK / I2S_BLK	I/O	PCM/I2S clock, can be output (if central) or input (if peripheral)	GPIO[4]
PCM_SYNC / I2S_LRCLK	I/O	PCM/I2S sync, can be output (if central) or input (if peripheral)	GPIO[7]
PCM_MCLK / I2S_CCLK	O	Optional clock pins	GPIO[3]

Table 17: Bluetooth PCM/I2S interface description

2.7.1 Central mode

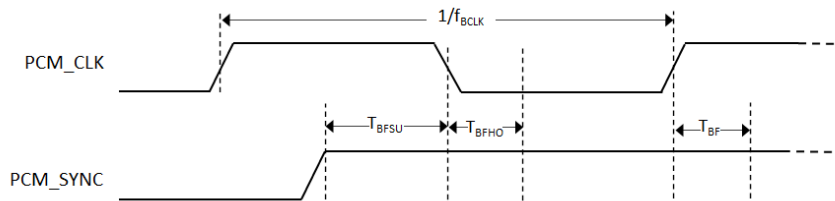


Figure 12: PCM timing specification diagram for PCM_SYNC signal – Central mode

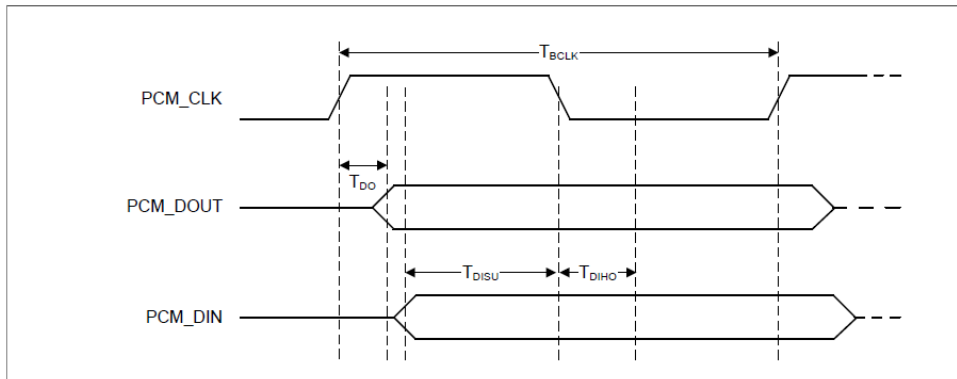


Table 18: PCM timing specification diagram for data signals – Central mode

Symbol	Parameter	Condition	Min	Typ	Max	Unit
F_{BCLK}	Bit clock frequency	–	2	2/2.048	2.048	MHz
Duty Cycle $BCLK$	Bit clock duty cycle	–	0.4	0.5	0.6	–
$T_{BCLK\ rise/fall}$	PCM_CLK rise/fall time	–	–	3	–	ns
T_{DO}	Delay from PCM_CLK rising edge to PCM_DOUT rising edge	–	–	–	15	ns
T_{DISU}	Setup time for PCM_DIN before PCM_CLK falling edge	–	20	–	–	ns
T_{DIHO}	Hold time for PCM_DIN after PCM_CLK falling edge	–	15	–	–	ns
T_{BF}	Delay from PCM_CLK rising edge to PCM_SYNC rising edge	–	–	–	15	ns

Table 19: PCM timing specification data – Central mode

2.7.2 Peripheral mode

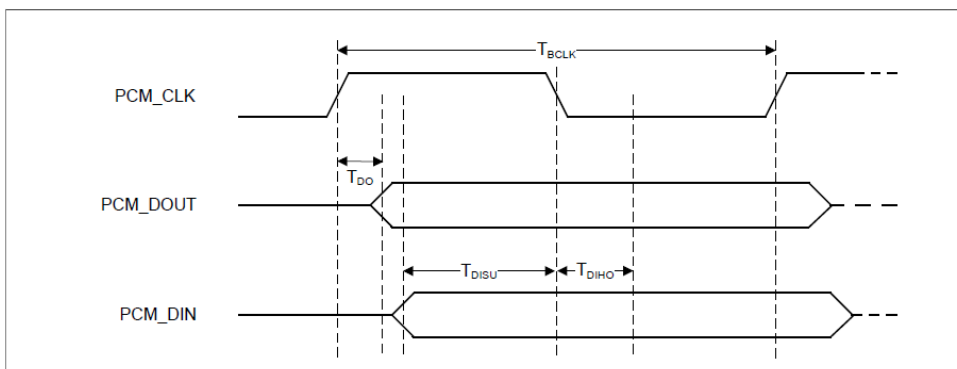


Figure 13: PCM timing specification diagram for data signals – Peripheral mode

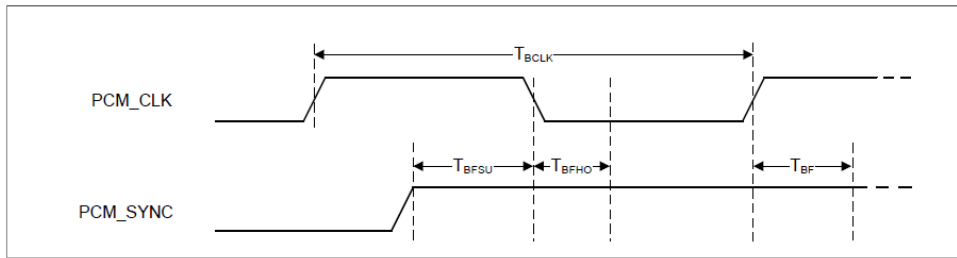


Figure 14: PCM timing specification diagram for PCM_SYNC signal – Peripheral mode

Symbol	Parameter	Condition	Min	Typ	Max	Unit
F_{BCLK}	Bit clock frequency	–	0.512	2/2.048	4	MHz
Duty Cycle _{BCLK}	Bit clock duty cycle	–	0.4	0.5	0.6	–
$T_{BCLK\ rise/fall}$	PCM_CLK rise/fall time	–	–	3	–	ns
T_{DO}	Delay from PCM_CLK rising edge to PCM_DOUT rising edge	–	–	–	30	ns
T_{DISU}	Setup time for PCM_DIN before PCM_CLK falling edge	–	15	–	–	ns
T_{DIHO}	Hold time for PCM_DIN after PCM_CLK falling edge	–	10	–	–	ns
T_{BFSU}	Setup time for PCM_SYNC before PCM_CLK falling edge	–	15	–	–	ns
T_{BFHO}	Hold time for PCM_SYNC after PCM_CLK falling edge	–	10	–	–	ns

Table 20: PCM timing specification data – Peripheral mode

2.8 PTA/WCI-2 external coexistence interfaces

External coexistence interfaces enable signaling between the internal radios and external co-located wireless devices for optimal performance when sharing the wireless medium. External radios can be connected to the 5-wire packet traffic arbitration interface (PTA) shared with SPI on MAYA-W271 and -W276 or the 2-wire wireless coexistence interface 2 (WCI-2). The WCI-2 message format and message type comply with Bluetooth special interest group (SIG) core specification volume 7, part C.

Pin name	I/O type	Description	GPIO pin multiplexing
EXT_STATE	I	External radio state input signal External radio traffic direction (Tx/Rx): 1: Tx 0: Rx	GPIO[12]
EXT_GNT	O	External radio grant output signal	GPIO[14]
EXT_FREQ	I	External radio frequency input signal Frequency overlap between external radio and Wi-Fi: 1: overlap 0: non-overlap This signal is useful when the external radio is a frequency hopping device.	GPIO[20]
EXT_PRI	I	External radio input priority signal Priority of the request from the external radio. Can support 1 bit priority (sample once) and 2-bit priority (sample twice). Can also have Tx/Rx information following the priority information if EXT_STATE is not used.	GPIO[15]
EXT_REQ	I	Request from the external radio	GPIO[13]

Table 21: PTA external coexistence interface description

Pin name	I/O type	Description	GPIO pin multiplexing
WCI-2_SIN	I	WCI-2 serial interface input	GPIO[25]
WCI-2_SOUT	O	WCI-2 serial interface output	GPIO[26]

Table 22: WCI external coexistence interface description

2.9 JTAG

The module includes a JTAG test interface that is supported using the GPIO pins.

Pin name	I/O type	Description	GPIO pin multiplexing
JTAG_TCK	I	JTAG test clock input signal	GPIO[28]
JTAG_TMS	I	JTAG controller select input signal	GPIO[29]
JTAG_TDI	I	JTAG test data input signal	GPIO[30]
JTAG_TDO	O	JTAG test data output signal	GPIO[31]

Table 23: JTAG interface description

3 Pin definition

3.1 Pin assignment

M	GND	GND						GND	GND
L	ANT FEED								GND
K	RF ANT1	GND	GND	GND	NC	GND	GND	GND	RF ANT0
J	BT/15.4 DEV WAKE	WL DEV WAKE	BT/15.4 RST	JTAG TMS	JTAG TCK		PDn	NC	NC
H	UART RTS	UART CTS	WL RST	GND	GND		RF CNTL0	NC	NC
G	UART TX	UART RX	JTAG TDI	JTAG TDO	RF CNTL2		RF CNTL4	SPI RX	NC
F	PCM DOUT	PCM SYNC	WL WAKE HOST	GND	GND		RF CNTL3	SPI TX	NC
E	PCM DIN	PCM MCLK	BT/15.4 WAKE HOST	GND	GND		CONFIG [1]	SPI CLK	NC
D	NC	PCM CLK	SD INT				CONFIG [0]	SPI INT	NC
C	NC	RST IND		WCI SIN	NC	NC		SPI FRM	NC
B	NC	GND	3V3	WCI SOUT	SD DAT[2]	SD CMD	SD DAT[0]	GND	GPIO [27]
A	GND	VIO	3V3	VIO SD	SD DAT[3]	SD CLK	SD DAT[1]	1V8	GND
	9	8	7	6	5	4	3	2	1

Figure 15: MAYA-W2 series pin assignment (top view)

 All signal pins are mounted in a land grid array (LGA) package on the bottom side of the PCB. The RF pins (**RF_ANT0** and **RF_ANT1**) are not available on MAYA-W260.

No.	Name	Pin type ¹	Chipset pin	Description	Power Down	Power supply domain
A1	GND	GND		Ground	-	
A2	1V8	PWR		1.8 V supply	-	1V8
A3	SD_DAT[1]	I/O	SD_DAT[1]	SDIO data 1	Tristate	VIO_SD
A4	SD_CLK	I	SD_CLK	SDIO clock	Tristate	VIO_SD
A5	SD_DAT[3]	I/O	SD_DAT[3]	SDIO data 3	Tristate	VIO_SD
A6	VIO_SD	PWR		1.8 V / 3.3 V SDIO supply	-	VIO_SD
A7	3V3	PWR		3.3 V supply	-	3V3
A8	VIO	PWR		1.8 V / 3.3 V I/O supply	-	VIO
A9	GND	GND		Ground	-	
B1	GPIO[27]	I/O	GPIO[27]	Multi-functional pin: - GPIO[27] - BLE ISOC trigger mode: Host trigger pin	Tristate	VIO
B2	GND	GND		Ground	-	
B3	SD_DAT[0]	I/O	SD_DAT[0]	SDIO data 0	Tristate	VIO_SD
B4	SD_CMD	I/O	SD_CMD	SDIO command/response	Tristate	VIO_SD
B5	SD_DAT[2]	I/O	SD_DAT[2]	SDIO data 2	Tristate	VIO_SD
B6	WCI_SOUT	I/O	GPIO[26]/ WCI-2_SOUT	Multi-functional pin: - GPIO[26] - WCI-2 coexistence serial interface output	Drive low	VIO
B7	3V3	PWR		3.3 V supply	-	3V3
B8	GND	GND		Ground	-	
B9	NC	NC		Reserved for VUSB	-	
C1	NC	NC		Reserved for PCIe	-	
C2	EXT_REQ/SPI_FRM	I/O	GPIO[13]/ SPI_FRM	Multi-functional pin: - GPIO[13] - SPI mode: SPI frame signal (input) - PTA mode: EXT_REQ - External radio request input signal	Drive high	VIO
C4	NC	NC		Reserved for I2C	-	
C5	NC	NC		Reserved for I2C	-	
C6	WCI_SIN	I/O	GPIO[25]/ WCI-2_SIN	Multi-functional pin: - GPIO[25] - WCI-2 coexistence serial interface input	Tristate	VIO
C8	RST_IND	I/O	GPIO[22]/ RST_IND	Multi-functional pin: - GPIO[22] - RST_IND - Bluetooth/802.15.4 independent software reset indicator to host (output)	Tristate	VIO
C9	NC	NC		Reserved for USB	-	
D1	NC	NC		Reserved for PCIe	-	
D2	EXT_FREQ/SPI_INT	I/O	GPIO[20]/ SPI_INT	Multi-functional pin: - GPIO[20] - SPI mode: SPI interrupt signal (output) - PTA mode: EXT_FREQ - External radio frequency input signal	Drive low	VIO
D3	CONFIG[0]	I	CONFIG_HOST_ BOOT[0]	Configuration pin: CON[0]	Tristate	1V8

¹ I/O notations: I=Input, O=Output, I/O=Input or Output, OD=Open Drain, NC=Not Connected, PWR=Power, GND=Ground, RF=Radio i/f

No.	Name	Pin type ¹	Chipset pin	Description	Power Down	Power supply domain
D7	SD_INT	I/O	GPIO[21]/ SD_INT	Multi-functional pin: - GPIO[21] - SD_INT: SDIO interrupt signal (output)	Drive low	VIO
D8	PCM_CLK	I/O	GPIO[4]/ PCM_CLK	Multi-functional pin: - GPIO[4] - PCM mode: PCM_CLK - PCM data clock - I2S mode: I2S_BCLK - I2S bit clock	Tristate	VIO
D9	NC	NC		Reserved for USB	-	
E1	NC	NC		Reserved for PCIe	-	
E2	EXT_STATE/SPI_CLK	I/O	GPIO[12]/ SPI_CLK	Multi-functional pin: - GPIO[12] - SPI mode: SPI clock signal (input) - PTA mode: EXT_STATE - External radio state input signal	Tristate	VIO
E3	CONFIG[1]	I	CONFIG_HOST_BOOT[0]	Configuration pin: CON[1]	Tristate	1V8
E4	GND	GND		Ground	-	
E5	GND	GND		Ground	-	
E7	BT_15.4_WAKE_HOST	I/O	GPIO[19]/ BT_15.4_WAKE_OUT	Multi-functional pin: - GPIO[19] - Bluetooth/802.15.4 to host wake-up signal (output)	Drive low	VIO
E8	PCM_MCLK	I/O	GPIO[3]/ PCM_MCLK	Multi-functional pin: - GPIO[3] - PCM/I2S codec main clock output signal (optional)	Tristate	VIO
E9	PCM_DIN	I/O	GPIO[6]/ PCM_DIN	Multi-functional pin: - GPIO[6] - PCM/I2S mode: PCM/I2S receive data signal (input)	Tristate	VIO
F1	NC	NC		Reserved for PCIe	-	
F2	EXT_PRI/SPI_TX	I/O	GPIO[15]/ SPI_TXD	Multi-functional pin: - GPIO[15] - SPI mode: SPI transmit signal (output) - PTA mode: EXT_PRI - External radio priority input signal	Drive low	VIO
F3	RF_CNTL3	I/O	RF_CNTL3/ CONFIG_XOSC_SEL	RF control, used to control an external Wi-Fi antenna diversity switch Configuration pin: CON[5]	Drive high	VIO
F4	GND	GND		Ground	-	
F5	GND	GND		Ground	-	
F7	WL_WAKE_HOST	I/O	GPIO[17]/ WL_WAKE_OUT	Multi-functional pin: - GPIO[17] - Wi-Fi radio to host wake-up signal (output)	Drive low	VIO
F8	PCM_SYNC	I/O	GPIO[7]/ PCM_SYNC	Multi-functional pin: - GPIO[7] - PCM mode: PCM_SYNC - PCM frame sync - I2S mode: I2S_LRCLK - I2S left/right clock	Tristate	VIO
F9	PCM_DOUT	I/O	GPIO[5]/ PCM_DOUT	Multi-functional pin: - GPIO[5] - PCM/I2S mode: PCM/I2S transmit data signal (output)	Tristate	VIO

No.	Name	Pin type ¹	Chipset pin	Description	Power Down	Power supply domain
G1	NC	NC		Reserved for PCIe	-	
G2	EXT_GNT/SPI_RX	I/O	GPIO[14]/ SPI_RXD	Multi-functional pin: - GPIO[14] - SPI mode: SPI receive signal (input) - PTA mode: EXT_GNT - External radio grant output signal	Tristate	VIO
G3	RF_CNTL4	I/O	RF_CNTL4	RF control Configuration pin: CON[7]	Drive low	VIO
G4	RF_CNTL2	I/O	RF_CNTL2	RF control	Drive low	VIO
G5	JTAG_TDO	I/O	GPIO[31]/ JTAG_TDO	Multi-functional pin: - GPIO[31] - JTAG test data signal (output)	Tristate	VIO
G7	JTAG_TDI	I/O	GPIO[30]/ JTAG_TDI	Multi-functional pin: - GPIO[30] - JTAG test data signal (input)	Tristate	VIO
G8	UART_RX	I/O	GPIO[10]/ UART_RX	Multi-functional pin: - GPIO[10] - UART serial input signal	Tristate	VIO
G9	UART_TX	I/O	GPIO[11]/ UART_TX	Multi-functional pin: - GPIO[11] - UART serial output signal	Drive low	VIO
H1	NC	NC		Reserved for PCIe	-	
H2	NC	NC		Reserved for PCIe	-	
H3	RF_CNTL0	I/O	RF_CNTL0	RF control	Drive low	VIO
H4	GND	GND		Ground	-	
H5	GND	GND		Ground	-	
H7	WL_RST	I/O	GPIO[1]/ IND_RST_WL	Multi-functional pin: - GPIO[1] - Independent software reset for Wi-Fi (input)	Tristate	VIO
H8	UART_CTS	I/O	GPIO[8]/ UART_CTS	Multi-functional pin: - GPIO[8] - UART clear-to-send input signal (active low)	Tristate	VIO
H9	UART_RTS	I/O	GPIO[9]/ UART_RTS	Multi-functional pin: - GPIO[9] - UART request-to-send output signal (active low)	Drive high	VIO
J1	NC	NC		Reserved for PCIe	-	
J2	NC	NC		Reserved for PCIe	-	
J3	PDn	I	PDn	Power Down Signal (input) 0 – power-down mode 1 – normal mode This pin has an always-on internal 10 kΩ pull-up on the module. It can accept an input of 1.8 – 4.5 V.	-	1V8
J4	JTAG_TCK	I/O	GPIO[28]/ JTAG_TCK	Multi-functional pin : - GPIO[28] - JTAG test clock signal (input)	Tristate	VIO
J5	JTAG_TMS	I/O	GPIO[29]/ JTAG_TMS	Multi-functional pin: - GPIO[29] - JTAG controller select (input)	Tristate	VIO

No.	Name	Pin type ¹	Chipset pin	Description	Power Down	Power supply domain
J7	BT_15.4_RST	I/O	GPIO[2]/ IND_RST_BT	Multi-functional pin: - GPIO[2] - Independent software reset for Bluetooth and 802.15.4 (input)	Tristate	VIO
J8	WL_DEV_WAKE	I/O	GPIO[16]/ WL_WAKE_IN	Multi-functional pin: - GPIO[16] - Wi-Fi radio wake-up signal (input)	Tristate	VIO
J9	BT_15.4_DEV_WAKE	I/O	GPIO[18]/ BT_15.4_WAKE_IN	Multi-functional pin: - GPIO[18] - Bluetooth/802.15.4 radio wake-up signal (input)	Tristate	VIO
K1	RF_ANT0	RF		Wi-Fi I/O (only in MAYA-W261 and MAYA-W271)	-	
K2	GND	GND		Ground	-	
K3	GND	GND		Ground	-	
K4	GND	GND		Ground	-	
K5	NC	NC		Reserved for RF_ANT	-	
K6	GND	GND		Ground	-	
K7	GND	GND		Ground	-	
K8	GND	GND		Ground	-	
K9	RF_ANT1	RF		MAYA-W261: Bluetooth I/O MAYA-W271: Bluetooth/802.15.4 I/O MAYA-W266: Combined Bluetooth and Wi-Fi I/O MAYA-W276: Combined Bluetooth, 802.15.4, and Wi-Fi I/O	-	
L1	GND	GND		Ground	-	
L9	ANT_FEED	RF		External antenna feed pin for embedded PCB antenna on MAYA-W266 and W276 Others: NC	-	
M1	GND	GND		Ground	-	
M2	GND	GND		Ground	-	
M8	GND	GND		Ground	-	
M9	GND	GND		Ground	-	

Table 24: MAYA-W2 series pin description

4 Electrical specifications

Stressing the device above one or more of the ratings of the [Absolute maximum ratings](#) can cause permanent damage. These are stress ratings only. Operating the module at these ratings or in conditions other than those specified in the [Operating conditions](#) should be avoided. Exposure to absolute maximum rating conditions for extended periods can affect device reliability.

All given application information is only advisory and does not form part of the specification.

4.1 Absolute maximum ratings

Symbol	Description	Min.	Max.	Units
3V3	Power supply voltage	-	3.96	V
1V8	Power supply voltage 1.8 V	-	2.16	V
VIO	I/O supply voltage 1.8 V	-	2.16	V
	I/O supply voltage 3.3 V	-	3.96	V
VIO_SD	SDIO power supply voltage 1.8 V	-	2.16	V
	SDIO power supply voltage 3.3 V	-	3.96	V
T _{STORAGE}	Storage temperature	-55	+125	°C

Table 25: Absolute maximum ratings

The product is not protected against overvoltage or reversed voltages. If necessary, voltage spikes exceeding the power supply voltage specifications given in [Table 25](#) must be limited to values within the specified boundaries by using appropriate protection devices.

4.1.1 Maximum ESD ratings

Applicability	Min.	Max.	Units
Human Body Model (HBM), ANSA/ESDA/JEDEC JS-001-2014.	-2000	+2000	V
Charged Device Model (CDM), JESD22-C101.	-500	+500	V

Table 26: Maximum ESD ratings

4.2 Recommended operating conditions

Symbol	Parameter	Min.	Typ	Max.	Units
3V3	Power supply voltage	3.14	3.3	3.46	V
1V8	Power supply voltage 1.8 V	1.71	1.80	1.89	V
VIO	I/O supply voltage 1.8 V	1.71	1.80	1.89	V
	I/O supply voltage 3.3 V	3.14	3.30	3.46	V
VIO_SD	I/O supply voltage 1.8 V	1.71	1.80	1.89	V
	I/O supply voltage 3.3 V	3.14	3.30	3.46	V
T _A	Ambient operating temperature for professional grade modules	-40		+85	°C
	Ambient operating temperature for standard grade modules	0		+70	°C
T _J	Maximum junction temperature	-	-	125	°C

Table 27: Operating conditions

4.3 Digital pad settings

Symbol	Parameter	V _{IO}	Min.	Max.	Units
V _{IH}	Input high voltage	1.8 V / 3.3 V	0.7*V _{IO}	V _{IO} +0.4	V
V _{IL}	Input low voltage	1.8 V / 3.3 V	-0.4	0.3*V _{IO}	V
V _{HYS}	Input hysteresis	1.8 V / 3.3 V	100	-	mV
V _{OH}	Output high voltage	1.8 V / 3.3 V	V _{IO} -0.4	-	V
V _{OL}	Output low voltage	1.8 V / 3.3 V	-	0.4	V

Table 28: DC characteristics V_{IO}

4.4 Power consumption

4.4.1 Wi-Fi power consumption

 Unless otherwise stated, all specifications are valid at 25° C and given at nominal voltage with typical SDIO clock speed of 200 MHz.

Wi-Fi operation modes	3V3 (3.3V) [mA]	1V8 (1.8 V) [mA]	V _{IO} +V _{IO_SD} (1.8 V) [mA]
Power – save modes ^[1]			
Power down	0.01	0.04	0.01
Wi-Fi only enabled in deep-sleep	0.01	1.80	0.04
Wi-Fi, Bluetooth and 802.15.4 in deep-sleep mode	0.02	0.41	0.12
Active transmit modes for 2G Wi-Fi operation ^[1]			
IEEE Power Save DTIM 10 and Bluetooth deep-sleep, 2G	0.02	0.72	0.06
IEEE Power Save DTIM 5 and Bluetooth deep-sleep, 2G	0.02	0.9	0.06
IEEE Power Save DTIM 3 and Bluetooth deep-sleep, 2G	0.02	1.14	0.06
IEEE Power Save DTIM 1 and Bluetooth deep-sleep, 2G	0.02	2.52	0.06
IEEE Power Save DTIM 10 and Bluetooth deep-sleep, 5G	0.02	0.66	0.06
IEEE Power Save DTIM 5 and Bluetooth deep-sleep, 5G	0.02	0.72	0.06
IEEE Power Save DTIM 3 and Bluetooth deep-sleep, 5G	0.02	0.91	0.06
IEEE Power Save DTIM 1 and Bluetooth deep-sleep, 5G	0.02	1.57	0.06
CCK 1 Mbit/s, BW20, Ch6, 21 dBm	261	168	0.1
CCK 11 Mbit/s, BW20, Ch6, 20 dBm	239	150	0.1
OFDM 54 Mbit/s, BW20, Ch6, 20dBm	234	182	0.1
OFDM 54 Mbit/s, BW20, Ch6, 19dBm	205	175	0.1
MCS0, HT20, Ch6, 20 dBm	235	189	0.1
MCS7, HT20, Ch6, 20 dBm	232	182	0.1
MCS0, HT40, Ch6, 20 dBm	249	194	0.1
MCS7, HT40, Ch6, 20 dBm	233	183	0.1
MCS0, HE20, Ch6, 20 dBm	247	189	0.1
MCS11, HE20, Ch6, 20 dBm	221	180	0.1
MCS0, HE40, Ch6, 20 dBm	258	199	0.1
MCS11, HE40, Ch6, 20 dBm	212	183	0.1

Wi-Fi operation modes	3V3 (3.3V) [mA]	1V8 (1.8 V) [mA]	VIO+VIO_SD (1.8 V) [mA]
Active transmit modes for 5G Wi-Fi operation ^[1]			
OFDM 6 Mbit/s, BW20, Ch100, 19 dBm	279	224	0.1
OFDM 54 Mbit/s, BW20, Ch100, 19 dBm	260	220	0.1
MCS0, HT20, Ch100, 19 dBm	287	229	0.1
MCS7, HT20, Ch100, 19 dBm	269	219	0.1
MCS0, VHT20, Ch100, 19 dBm	293	229	0.1
MCS8, VHT20, Ch100, 19 dBm	265	217	0.1
MCS0, HE20, Ch100, 19 dBm	269	229	0.1
MCS11, HE20, Ch100, 19 dBm	246	220	0.1
MCS0, HT40, Ch102, 17 dBm	219	232	0.1
MCS7, HT40, Ch102, 17 dBm	185	211	0.1
MCS0, VHT40, Ch102, 17 dBm	244	235	0.1
MCS9, VHT40, Ch102, 17 dBm	217	220	0.1
MCS0, HE40, Ch102, 17 dBm	221	232	0.1
MCS11, HE40, Ch102, 17 dBm	184	209	0.1
MCS0, VHT80, Ch106, 15 dBm	201	229	0.1
MCS9, VHT80, Ch106, 15 dBm	218	188	0.1
MCS0, HE80, Ch106, 15 dBm	212	236	0.1
MCS11, HE80, Ch106, 15 dBm	193	227	0.1
Receive modes for 2G Wi-Fi operation ^[1]			
CCK 11 Mbit/s, BW20, Ch6, -50 dBm	0.1	103	0.1
OFDM 54 Mbit/s, BW20, Ch6, -50 dBm	0.1	103	0.1
MCS7, HT20, Ch6, -50 dBm	0.1	103	0.1
MCS11, HE20, Ch6, -50 dBm	0.1	103	0.1
MCS7, HT40, Ch6, -50 dBm	0.1	113	0.1
MCS11, HE40, Ch6, -50 dBm	0.1	113	0.1
Receive modes for 5G Wi-Fi operation ^[1]			
OFDM 54, BW20, Ch100, -50dBm	0.1	119	0.1
MCS7, HT20, Ch100, -50 dBm	0.1	119	0.1
MCS8, VHT20, Ch100, -50 dBm	0.1	119	0.1
MCS11, HE20, Ch100, -50 dBm	0.1	119	0.1
MCS7, HT40, Ch102, -50 dBm	0.1	135	0.1
MCS9, VHT40, Ch102, -50 dBm	0.1	135	0.1
MCS11, HE40, Ch102, -50 dBm	0.1	135	0.1
MCS9, VHT80, Ch106, -50 dBm	0.1	165	0.1
MCS11, HE80, Ch106, -50 dBm	0.1	165	0.1
Peak current (at room temperature)			
Active transmission	400	1000	2
Firmware initialization	0.4	129	0.1

Table 29: Typical Wi-Fi radio current consumption with different modes of operation

4.4.2 Bluetooth power consumption

Unless otherwise stated, all specifications are valid at 25° C and given at nominal voltage with typical SDIO clock speed of 200 MHz.

Bluetooth operation modes	3V3 (3.3 V) [mA]	1V8 (1.8 V) [mA]	VIO+VIO_SD (1.8 V) [mA]
Operating modes ^[1]			
Bluetooth and 802.15.4 only in deep sleep	0.02	0.25	0.06
Bluetooth in idle (without deep sleep)	0.01	11.2	0.02
Bluetooth classic inquiry scan	0.02	1.0	0.1
Bluetooth classic page scan	0.02	0.7	0.1
Bluetooth LE advertisement (interval = 1.28 s)	0.02	0.3	0.1
Bluetooth LE scanning (interval = 1.28 s, window = 11.25 ms)	0.02	0.6	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 0 dBm	0.1	79	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 4 dBm	0.1	99	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 10 dBm	0.1	130	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 13 dBm	0.1	144	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 16 dBm	0.1	293	0.1
Bluetooth BDR 1DH5, 1 Mbit/s, Ch39, 20 dBm	0.1	348	0.1
Bluetooth EDR 3DH5, 3 Mbit/s, Ch39, 0 dBm	0.1	62	0.1
Bluetooth EDR 3DH5, 3 Mbit/s, Ch39, 3 dBm	0.1	79	0.1
Bluetooth EDR 3DH5, 3 Mbit/s, Ch39, 9 dBm	0.1	135	0.1
BLE, 1 Mbit/s, Ch1, 0 dBm	0.1	53	0.1
BLE, 1 Mbit/s, Ch1, 4 dBm	0.1	63	0.1
BLE, 1 Mbit/s, Ch1, 10 dBm	0.1	87	0.1
BLE, 1 Mbit/s, Ch1, 13 dBm	0.1	117	0.1
BLE, 1 Mbit/s, Ch1, 16 dBm	0.1	140	0.1
BLE, 1 Mbit/s, Ch1, 20 dBm	0.1	189	0.1
Active receive mode ^[1]			
Bluetooth, BDR, DH1	0.1	42	0.1
Bluetooth, BDR, DH5	0.1	42	0.1
Bluetooth, EDR, 2DH5	0.1	42	0.1
Bluetooth, EDR, 3DH5	0.1	42	0.1
Bluetooth Low Energy, 1 Mbit/s	0.1	42	0.1
Bluetooth Low Energy, 2 Mbit/s	0.1	42	0.1

Table 30: Typical Bluetooth current consumption with different modes of operation

4.4.3 802.15.4 power consumption

Unless otherwise stated, all specifications are valid at 25° C and given at nominal voltage with typical SDIO clock speed of 200 MHz.

802.15.4 operation modes	3V3 (3.3 V) [mA]	1V8 (1.8 V) [mA]	VIO+VIO_SD (1.8 V) [mA]
Operating modes			
802.15.4 transmit, 0 dBm	0.05	121	0.1
802.15.4 transmit, 10 dBm	0.05	187	0.1
802.15.4 transmit, 21 dBm	0.05	437	0.1
Active receive mode			
802.15.4 peak receive idle mode	0.05	31	0.1
802.15.4 peak receive active mode	0.05	31	0.1

Table 31: Typical 802.15.4 current consumption

4.5 Radio specification

4.5.1 Bluetooth

Parameter	Specification (typical values)
RF Frequency Range	2.402 – 2.480 GHz
Supported Modes	Bluetooth 5.3 Bluetooth Low Energy (LE) - LE long range coded PHY - Shared RF with BDR/EDR - LE 2 Mbit/s PHY
Modulation	1 Mbit/s: GFSK (BDR) 2 Mbit/s: $\pi/4$ DQPSK (EDR) 3 Mbit/s: 8DQPSK (EDR)
Transmit Power ^[1] ^[2] ^[3]	Class 1 BDR: 19 dBm
	Class 2 BDR: 3 dBm
	Class 1 EDR: 9 dBm
	Class 2 EDR: 3 dBm
	Bluetooth LE 1M and 2M: 19 dBm
Receiver sensitivity ^[1] ^[2]	Bluetooth LE Coded: 14 dBm
	Bluetooth BDR 1DH1: -93 dBm
	Bluetooth EDR 2DH1: -93 dBm
	Bluetooth EDR 3DH1: -87 dBm
	Bluetooth LE Coded 125 kb/s: -104 dBm
	Bluetooth LE Coded 500 kb/s: -103 dBm
	Bluetooth LE 1M: -99 dBm Bluetooth LE 2M: -97 dBm

Table 32: Bluetooth radio parameters

[1] Values are valid at Antenna pin ports and at room temperature.

[2] Single antenna variants, MAYA-W266 and MAYA-W276, typically have output power values up to 2 dBm lower.

[3] Bluetooth transmit power must be limited to ≤ 10 dBm e.i.r.p. to comply with EN 300 328 regulations.

4.5.2 IEEE 802.15.4

Parameter	Specification (typical Values)
RF Frequency Range	2.405 – 2.480 GHz
Supported Mode	IEEE 802.15.4-2020 - Support for Thread in 2.4 GHz band - Support for Matter over Thread
Modulation	O-QPSK
Transmit Power	Transmit Power up to 21 dBm, Channel 26: 0 dBm
Receiver sensitivity ^{[1][2]}	Channel 11 (2405 MHz): -101 dBm Channel 12 (2410 MHz): -101 dBm Channel 13 (2415 MHz): -101 dBm Channel 14 (2420 MHz): -101 dBm Channel 15 (2425 MHz): -101 dBm Channel 16 (2430 MHz): -101 dBm Channel 17 (2435 MHz): -101 dBm Channel 18 (2440 MHz): -100 dBm Channel 19 (2445 MHz): -101 dBm Channel 20 (2450 MHz): -101 dBm Channel 21 (2455 MHz): -101 dBm Channel 22 (2460 MHz): -101 dBm Channel 23 (2465 MHz): -101 dBm Channel 24 (2470 MHz): -101 dBm Channel 25 (2475 MHz): -101 dBm Channel 26 (2480 MHz): -100 dBm

Table 33: IEEE 802.15.4 parameters

[1] Values are valid at Antenna pin ports and at room temperature.

[2] Single antenna variants, MAYA-W266 and MAYA-W276, typically have output power values up to 2 dBm lower.

4.5.3 Wi-Fi

MAYA-W2 series modules support dual-band Wi-Fi with 802.11a/b/g/n/ac/ax operation in the 2.4 GHz and 5 GHz radio bands. The module is designed to operate in only one frequency band at a time.

Parameter	Operation Mode	Specification
RF Frequency range	802.11b/g/n/ax	2.400 – 2.500 GHz
	802.11a/n/ac/ax	4.900 – 5.895 GHz
Modulation	802.11b	CCK and DSSS
	802.11a/g/n/ac/ax	OFDM
Supported data rates	802.11b	1, 2, 5.5, 11 Mbit/s
	802.11a/g	6, 9, 12, 18, 24, 36, 48, 54 Mbit/s
	802.11n	MCS0 – MCS7
	802.11ac	MCS0 – MCS9
	802.11ax	MCS0 – MCS11
Supported channel bandwidth	802.11b/g	20 MHz
	802.11n	20, 40 MHz
	802.11ac/ax	20, 40, 80 MHz
Supported guard interval (GI)	802.11ax	800, 1600, 3200 ns

Table 34: Wi-Fi radio parameters

Parameter	Operation mode	802.11 EVM limit	Specification (typical output power tolerance ± 2 dB) ^[1]	
			Dual Antenna Variants (20/40/80 MHz)	Single antenna variants (20/40/80 MHz)
Maximum transmit power	2.4 GHz	DSSS/CCK	-9 dB	18 dBm / - / -
		OFDM, BPSK	-5 dB	18 dBm / 17 dBm / -
		OFDM, QPSK	-13 dB	18 dBm / 17 dBm / -
		OFDM, 16-QAM	-19 dB	18 dBm / 17 dBm / -
		OFDM, 64-QAM, 3/4	-25 dB	18 dBm / 17 dBm / -
		OFDM, 64-QAM, 5/6	-27 dB	17 dBm / 17 dBm / -
		OFDM, 1024-QAM, 3/4	-35 dB	17 dBm / 16 dBm / -
		OFDM, 1024-QAM, 5/6	-35 dB	16 dBm / 16 dBm / -
	5 GHz	OFDM, BPSK	-5 dB	18 dBm / 18 dBm / 17 dBm
		OFDM, QPSK	-13 dB	18 dBm / 18 dBm / 16 dBm
		OFDM, 16-QAM	-19 dB	18 dBm / 18 dBm / 16 dBm
		OFDM, 64-QAM, 3/4	-25 dB	18 dBm / 18 dBm / 16 dBm
		OFDM, 64-QAM, 5/6	-27 dB	17 dBm / 17 dBm / 15 dBm
		OFDM, 256-QAM, 3/4	-30 dB	16 dBm / 16 dBm / 14 dBm
		OFDM, 256-QAM, 5/6	-32 dB	15 dBm / 15 dBm / 13 dBm
		OFDM, 1024-QAM, 3/4	-35 dB	14 dBm / 14 dBm / 12 dBm
		OFDM, 1024-QAM, 5/6	-35 dB	13 dBm / 13 dBm / 11 dBm

Table 35: Target Wi-Fi radio maximum transmit power parameters

Band	Operating mode	Data rate	Bandwidth	Specification (typical values tolerance ± 2 dBm) ^[1]
2.4 GHz	802.11b	1 Mbit/s / 2 Mbit/s	20 MHz	-93 dBm / -92 dBm
		5.5 Mbit/s / 11 Mbit/s		-90 dBm / -87 dBm
	802.11g	6 Mbit/s / 9 Mbit/s	20 MHz	-90 dBm / -89 dBm
		12 Mbit/s / 18 Mbit/s		-88 dBm / -86 dBm
		24 Mbit/s / 36 Mbit/s		-83 dBm / -80 dBm
		48 Mbit/s / 54 Mbit/s		-75 dBm / -74 dBm
	802.11n	MCS0 / MCS1	20 MHz	-90 dBm / -88 dBm
		MCS2 / MCS3		-85 dBm / -82 dBm
		MCS4 / MCS5		-79 dBm / -75 dBm
		MCS6 / MCS7		-73 dBm / -72 dBm
		MCS0 / MCS1	40 MHz	-87 dBm / -86 dBm
		MCS2 / MCS3		-84 dBm / -80 dBm
		MCS4 / MCS5		-77 dBm / -73 dBm
		MCS6 / MCS7		-71 dBm / -70 dBm
	802.11ax	MCS0 / MCS1	20 MHz	-90 dBm / -88 dBm
		MCS2 / MCS3		-87 dBm / -84 dBm
		MCS4 / MCS5		-81 dBm / -77 dBm

Band	Operating mode	Data rate	Bandwidth	Specification (typical values tolerance ± 2 dBm) ^[1]
5 GHz		MCS6 / MCS7	40 MHz	-75 dBm / -74 dBm
		MCS8 / MCS9		-70 dBm / -69 dBm
		MCS10 / MCS11		-64 dBm / -62 dBm
		MCS0 / MCS1		-87 dBm / -86 dBm
		MCS2 / MCS3		-85 dBm / -82 dBm
		MCS4 / MCS5		-79 dBm / -75 dBm
		MCS6 / MCS7		-73 dBm / -72 dBm
		MCS8 / MCS9		-68 dBm / -66 dBm
		MCS10 / MCS11		-63 dBm / -60 dBm
	802.11a	6 Mbit/s / 9 Mbit/s	20 MHz	-92 dBm / -92 dBm
		12 Mbit/s / 18 Mbit/s		-90 dBm / -88 dBm
		24 Mbit/s / 36 Mbit/s		-85 dBm / -82 dBm
		48 Mbit/s / 54 Mbit/s		-78 dBm / -76 dBm
		MCS0 / MCS1	20 MHz	-92 dBm / -90 dBm
		MCS2 / MCS3		-88 dBm / -84 dBm
		MCS4 / MCS5		-81 dBm / -77 dBm
		MCS6 / MCS7		-75 dBm / -74 dBm
	802.11n	MCS0 / MCS1	40 MHz	-90 dBm / -88 dBm
		MCS2 / MCS3		-86 dBm / -83 dBm
		MCS4 / MCS5		-79 dBm / -75 dBm
		MCS6 / MCS7		-74 dBm / -72 dBm
		MCS0 / MCS1	20 MHz	-92 dBm / -90 dBm
		MCS2 / MCS3		-88 dBm / -85 dBm
		MCS4 / MCS5		-82 dBm / -77 dBm
		MCS6 / MCS7		-76 dBm / -75 dBm
		MCS8		-70 dBm
		MCS0 / MCS1	40 MHz	-90 dBm / -88 dBm
		MCS2 / MCS3		-86 dBm / -83 dBm
		MCS4 / MCS5		-80 dBm / -76 dBm
		MCS6 / MCS7		-74 dBm / -73 dBm
	802.11ac	MCS8 / MCS9		-69 dBm / -67 dBm
		MCS0 / MCS1		-86 dBm / -85 dBm
		MCS2 / MCS3		-83 dBm / -80 dBm
		MCS4 / MCS5		-77 dBm / -73 dBm
		MCS6 / MCS7		-71 dBm / -70 dBm
		MCS8 / MCS9	80 MHz	-66 dBm / -64 dBm
		MCS0 / MCS1		-86 dBm / -85 dBm
		MCS2 / MCS3		-83 dBm / -80 dBm
		MCS4 / MCS5		-77 dBm / -73 dBm
		MCS6 / MCS7		-71 dBm / -70 dBm

Band	Operating mode	Data rate	Bandwidth	Specification (typical values tolerance ± 2 dBm) ^[1]
	802.11ax	MCS0 / MCS1	20 MHz	-93 dBm / -91 dBm
		MCS2 / MCS3		-89 dBm / -86 dBm
		MCS4 / MCS5		-83 dBm / -79 dBm
		MCS6 / MCS7		-78 dBm / -76 dBm
		MCS8 / MCS9		-72 dBm / -71 dBm
		MCS10 / MCS11		-66 dBm / -64 dBm
		MCS0 / MCS1	40 MHz	-90 dBm / -89 dBm
		MCS2 / MCS3		-87 dBm / -84 dBm
		MCS4 / MCS5		-81 dBm / 77 dBm
		MCS6 / MCS7		-76 dBm / -74 dBm
		MCS8 / MCS9		-70 dBm / -69 dBm
		MCS10 / MCS11		-66 dBm / -62 dBm
		MCS0 / MCS1	80 MHz	-87 dBm / -86 dBm
		MCS2 / MCS3		-84 dBm / -81 dBm
		MCS4 / MCS5		-79 dBm / -74 dBm
		MCS6 / MCS7		-74 dBm / -72 dBm
		MCS8 / MCS9		-68 dBm / -66 dBm
		MCS10 / MCS11		-63 dBm / -61 dBm

Table 36: Target Wi-Fi receiver characteristics

[1] Values are valid at Antenna pin ports and at room temperature.

4.5.4 Antenna radiation patterns

The radiation patterns displayed in [Table 37](#) and [Table 38](#) show the radiation patterns for MAYA-W266 and MAYA-W276 modules with on-board embedded niche antenna for 2.44 GHz and 5.5 GHz. [Table 39](#) shows the total radiated power (TRP) and peak gain for the low, mid, and high channel of the 2.4 GHz and 5 GHz frequency bands.

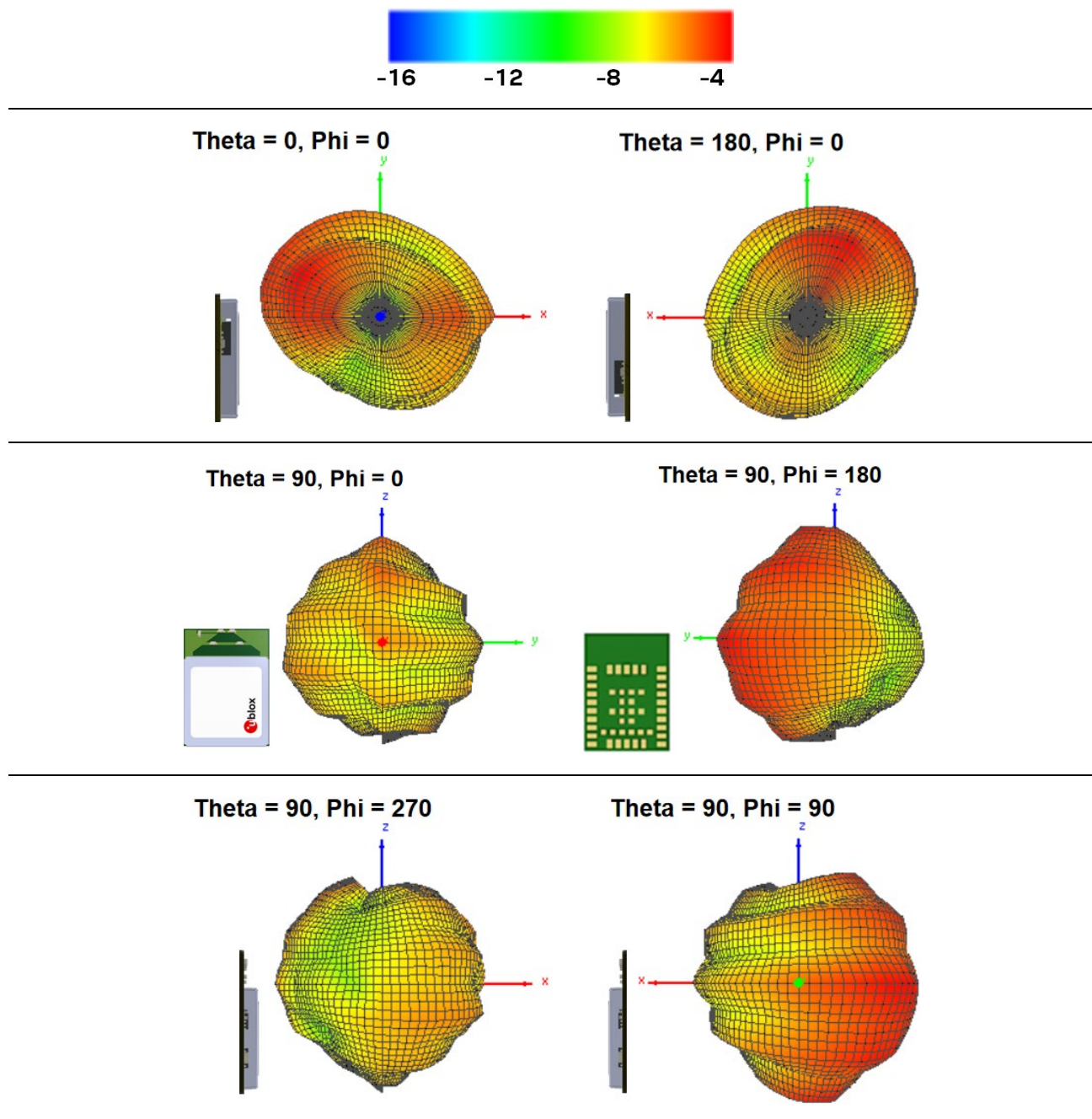
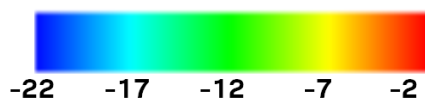
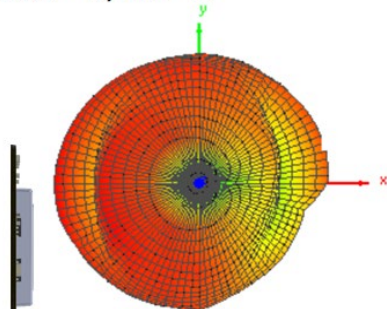


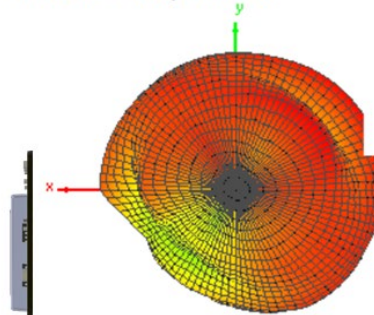
Table 37: Wi-Fi and Bluetooth antenna characteristics at 2.44 GHz



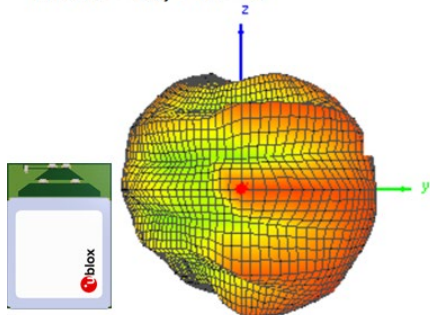
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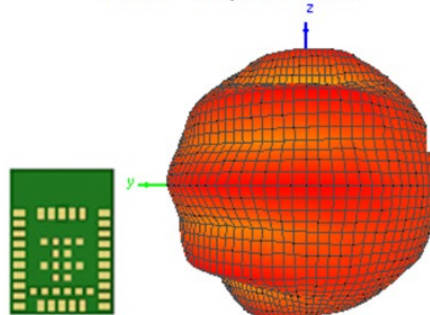
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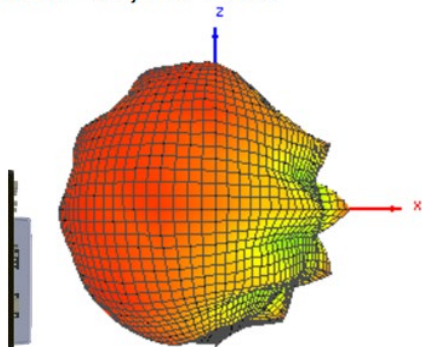
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Theta = 90, Phi = 180



Theta = 90, Phi = 270



Theta = 90, Phi = 90

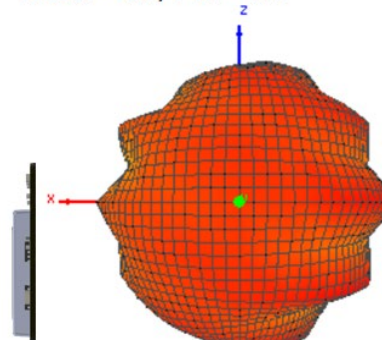


Table 38: Wi-Fi antenna characteristics at 5.50 GHz

Transmission	Measured TRP	Measured peak gain
Channel 1, 2.412 GHz	-7.99 dBm	-5.85 dBi
Channel 6, 2.437 GHz	-6.75 dBm	-4.62 dBi
Channel 13, 2.472 GHz	-6.64 dBm	-4.13 dBi
Channel 36, 5.180 GHz	-4.48 dBm	-2.77 dBi
Channel 100, 5.500 GHz	-2.53 dBm	-1.2 dBi
Channel 159, 5.795 GHz	-5.96 dBm	-3.83 dBi
Channel 177, 5.885 GHz	-8.76 dBm	-7.04 dBi

Table 39: Measured total radiated power and peak gain for 0 dBm transmission power

5 Software support

MAYA-W2 series modules are based on the NXP IW611 and NXP IW612 chipset and the drivers and firmware required to operate the modules are developed by NXP. A firmware binary is downloaded to the module by the host operating system driver at start-up.

The following software options are available for the MAYA-W2 module:

- Open-source Linux/Android driver (`mxm_mwiflex`) for mainstream use is available free of charge and already integrated into Linux BSP for NXP i.MX application processors
- MCUXpresso Wi-Fi/Bluetooth support for supported NXP MCUs

The software packages typically include:

- Dedicated kernel driver that binds the Wi-Fi device to the kernel. Driver sources are provided.
- Dedicated Wi-Fi firmware image that is uploaded during initialization of the Wi-Fi device.
- Dedicated Bluetooth firmware image that is uploaded during initialization of the Bluetooth device.
- Wi-Fi and Bluetooth release notes and a list of supported software features.
- Laboratory and manufacturing tools.

6 Mechanical specifications

6.1 MAYA-W2 footprint dimensions

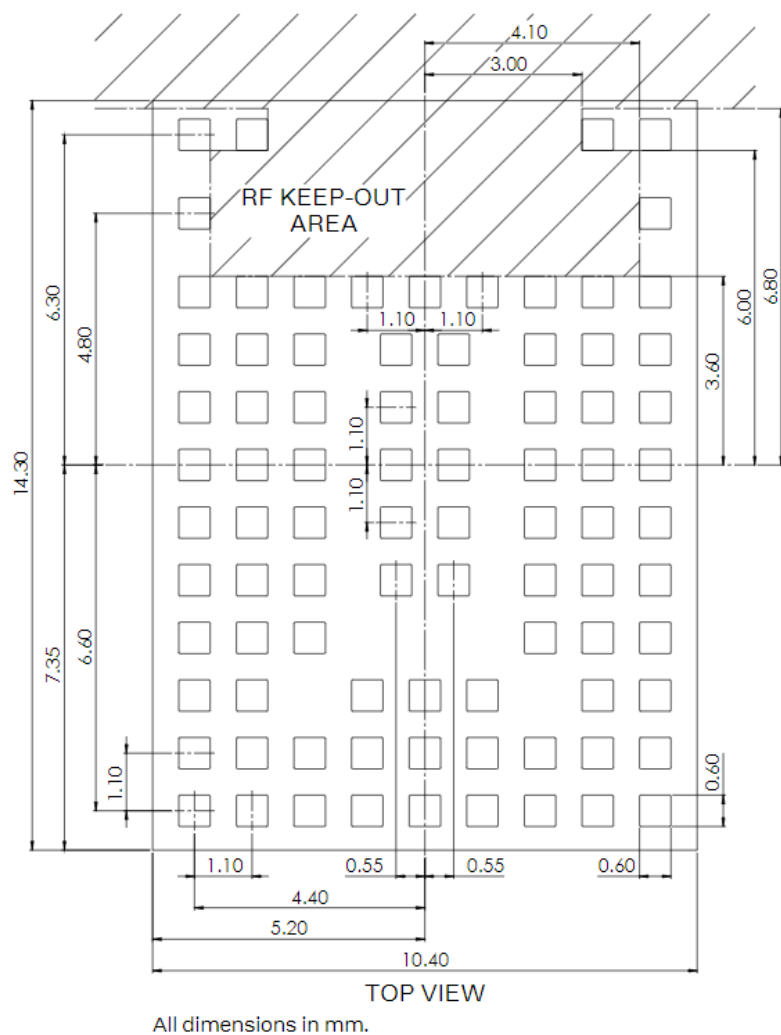


Figure 16: MAYA-W2 footprint

6.2 MAYA-W2 mechanical specifications

6.2.1 MAYA-W266 and MAYA-W276

Figure 17 and Figure 18 show the top and side views of MAYA-W266/-W276 module variants. All dimensions are shown in millimeters (mm).

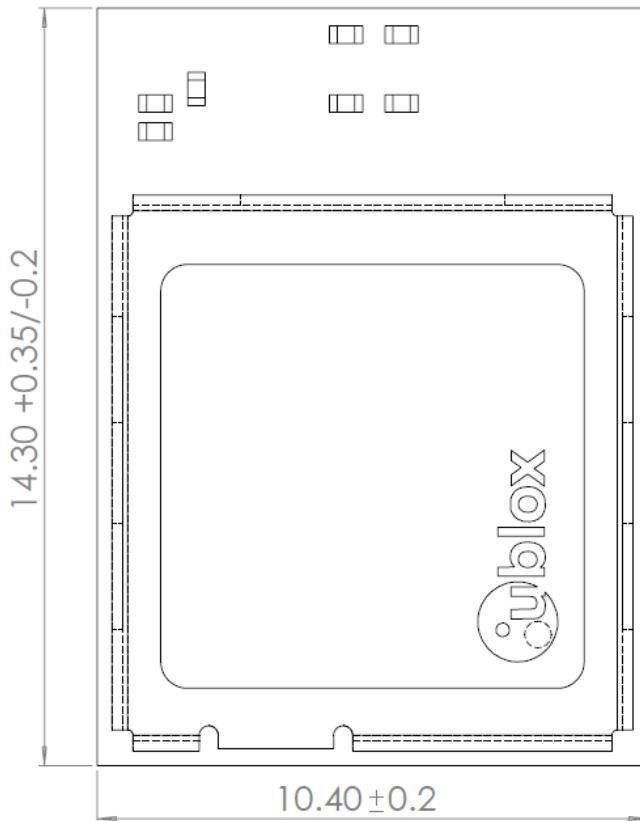


Figure 17: MAYA-W266/-W276 mechanical specifications (top view)

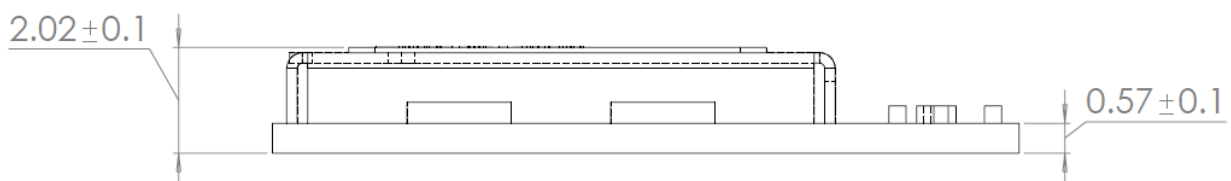


Figure 18: MAYA-W266/-W276 mechanical specifications (side view)

6.2.2 MAYA-W261 and MAYA-W271

Figure 19 and Figure 20 show the top and side views of MAYA-W261/-W271 module variants. All dimensions are shown in millimeters (mm).

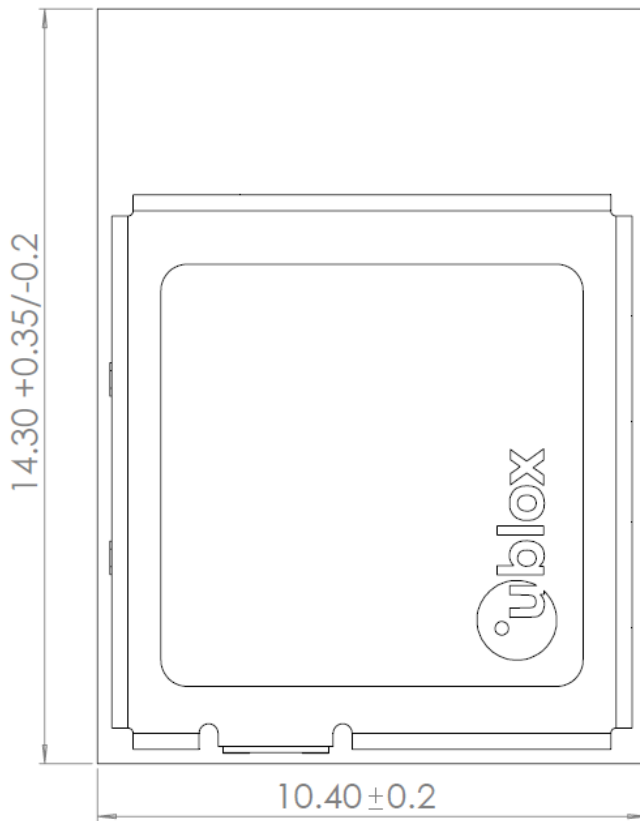


Figure 19: MAYA-W261/-W271 mechanical specifications (top view)

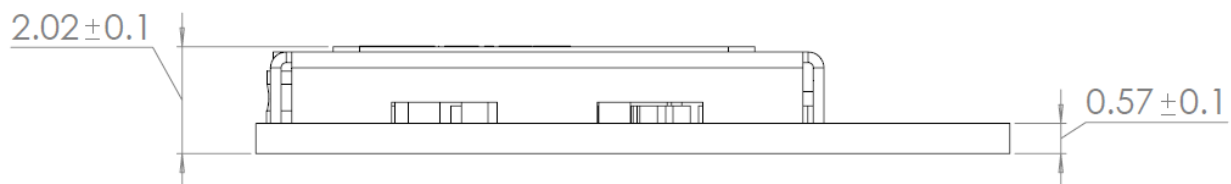


Figure 20: MAYA-W261/-W271 mechanical specifications (side view)

6.2.3 MAYA-W260

Figure 21 and Figure 22 show the top and side views of MAYA-W260. All dimensions are shown in millimeters (mm).

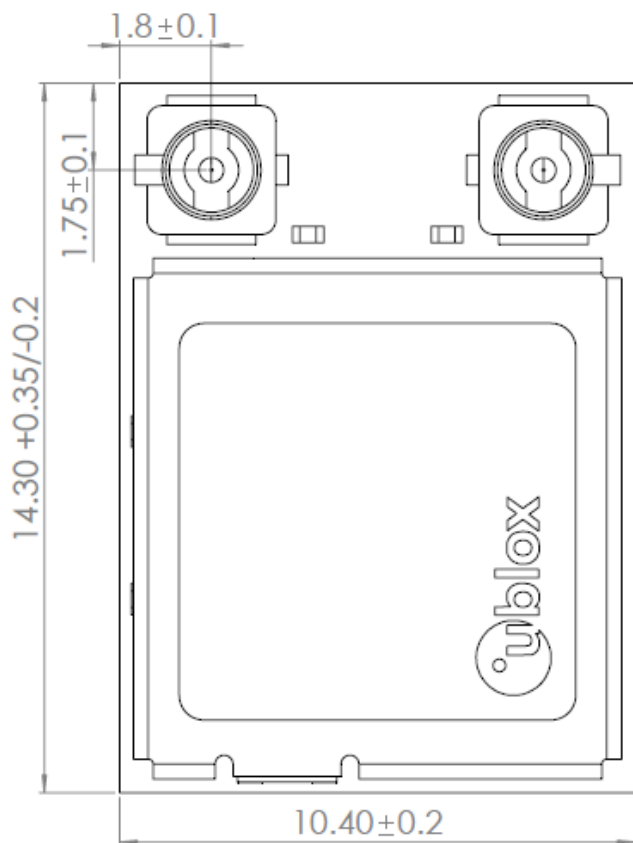


Figure 21: MAYA-W260 mechanical specifications (top view)

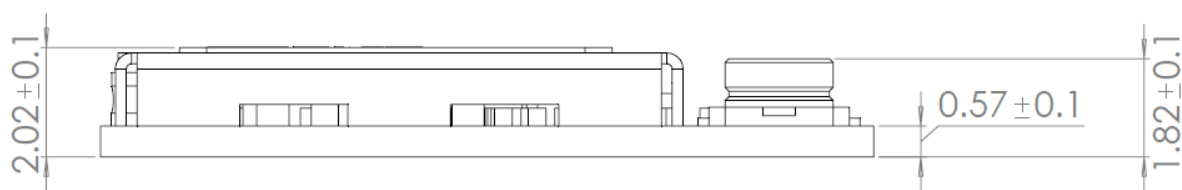


Figure 22: MAYA-W260 Mechanical Specifications (side view)

6.3 Module weight

Module	Typ	Unit
MAYA-W260	<1	g
MAYA-W261	<1	g
MAYA-W271	<1	g
MAYA-W266	<1	g
MAYA-W276	<1	g

Table 40: Module weight

7 Qualifications and approvals

The MAYA-W2 module series is certified for use in the countries/regions shown in [Table 41](#). Other country certifications can be scheduled on request.

Country/region	MAYA-W260	MAYA-W261	MAYA-W271	MAYA-W266	MAYA-W276
Europe (RED)	Approved	Approved	Approved	Approved	Approved
Great Britain (UKCA)	Approved	Approved	Approved	Approved	Approved
USA (FCC)	Approved	Approved	Approved	Approved	Approved
Canada (ISED)	Approved	Approved	Approved	Approved	Approved
Japan (Giteki)	Planned	Planned	Planned	Planned	Planned

Table 41: Certification

 For detailed information about the regulatory requirements that must be met when using MAYA-W2 modules in an end product, see the MAYA-W2 system integration manual [\[2\]](#).

7.1 Bluetooth qualification



End products must be qualified and listed with the [Bluetooth Special Interest Group \(SIG\)](#).

Product declarations are submitted through the [Bluetooth Launch Studio website](#).

MAYA-W2 series modules will be qualified as a Controller Subsystem in accordance with the Bluetooth 5.3 specification and registered with the SIG Qualified Design IDs (QDID) shown in [Table 42](#).

To list your product that integrates MAYA-W2 with no additional testing required, combine the QDID of the pre-qualified Controller Subsystem, as shown in [Table 42](#), with the QDID of a Bluetooth stack implemented in the Host Subsystem.

Model	Product type	QD ID	Listing date
MAYA-W260, MAYA-W261, MAYA-W266, MAYA-W271, MAYA-W276	Controller subsystem	-	Pending

Table 42: MAYA-W2 series Bluetooth qualified design IDs

8 Product handling

8.1 Packaging

MAYA-W2 series modules are delivered as hermetically sealed, reeled tapes to enable efficient production, production lot set-up and tear-down. For more information about packaging, see the Product packaging guide [1].

8.1.1 Reels

MAYA-W2 series modules are deliverable in quantities of 500 pieces on a reel. MAYA-W2 series modules are shipped on reel Type A3 as described in the Product packaging guide [1].

8.1.2 Tapes

Figure 23 shows the position and orientation of MAYA-W2 series modules as they are delivered on tape. The dimensions of the tapes are specified in Figure 24.

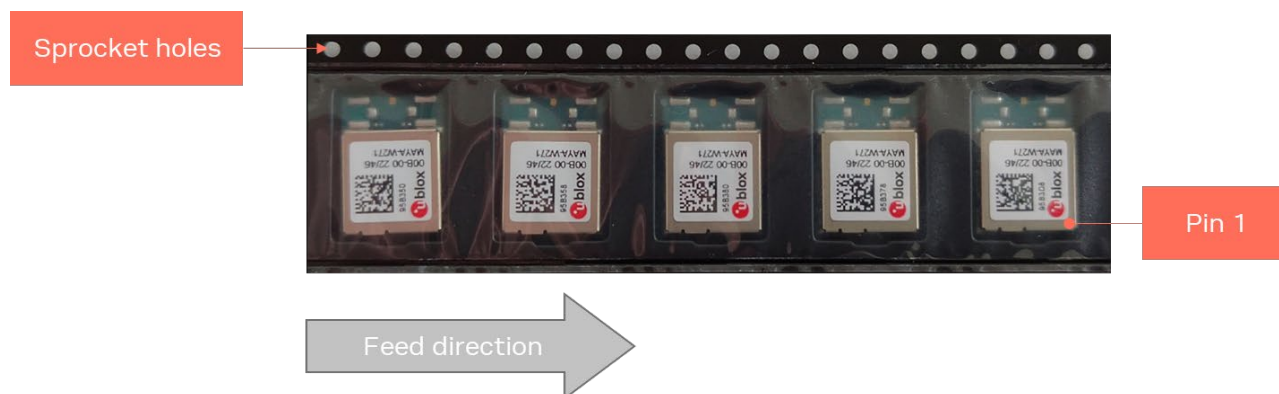


Figure 23: Orientation of MAYA-W2 modules on tape

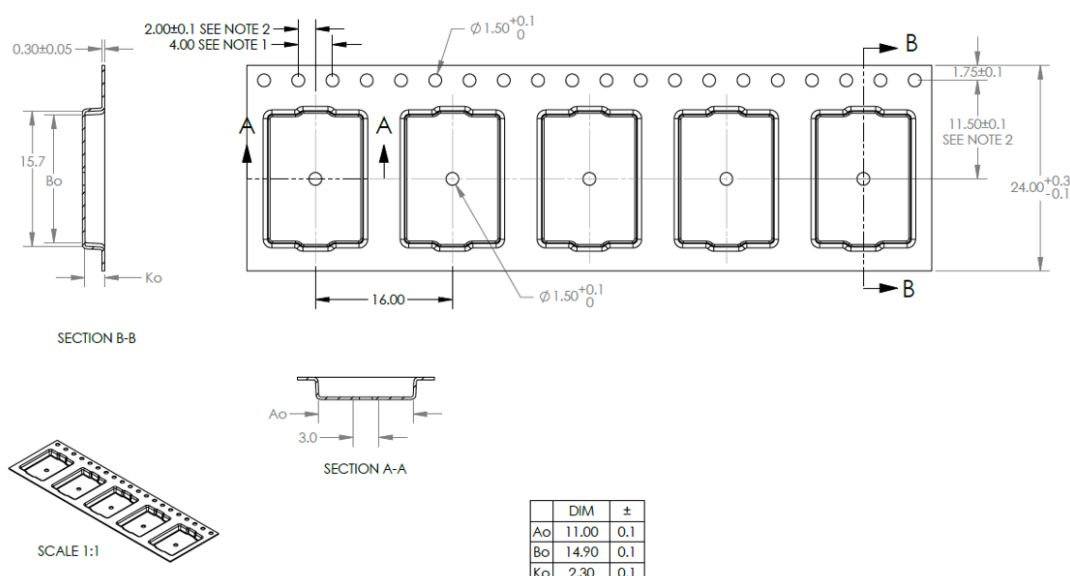


Figure 24: MAYA-W2 tape dimensions

8.2 Moisture sensitivity levels

-  MAYA-W2 series modules are rated as MSL Level 4 devices in accordance with the IPC/JEDEC J STD-020 standard. For detailed information, see the moisture sensitive warning label on the MBB (Moisture Barrier Bag).

After opening the dry pack, the modules must be mounted within 168 hours in factory conditions of maximum 30 °C/60%RH or must be stored at less than 10%RH. The modules require baking if the humidity indicator card shows more than 10% when read at 23±5 °C or if the conditions mentioned above are not met. For information about the bake procedure, see also the J-STD-033B standard.

For more information regarding MSL (Moisture Sensitivity Level), labeling, and storage, see also the Packaging information guide [\[1\]](#).

8.3 Reflow soldering

Reflow profiles must be selected in accordance with u-blox recommendations:

- MAYA-W260 is suitable for one-time reflow
- MAYA-W261, MAYA-W271, MAYA-W266, and MAYA-W276 are suitable for two-time reflow

-  Reflow soldering profiles must be selected in accordance with u-blox soldering recommendations described in the system integration manual [\[2\]](#). Failure to observe these recommendations can result in severe damage to the product.

8.4 ESD handling precautions

-  MAYA-W2 series modules are electrostatic sensitive devices (ESD) that demand adherence to special ESD precautions. Failure to observe these recommendations can result in severe damage to the product.

Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any application that incorporates MAYA-W2. We recommend that the module is not handled in a non-ESD protected environment. The RF antenna pins (**RF_ANT0** and **RF_ANT1**) are especially sensitive to ESD, and special care must be taken when connecting antennas. ESD safe soldering equipment is recommended.

9 Labeling and ordering information

9.1 Product labeling

The labels applied to MAYA-W2 series modules include important product information. [Figure 25](#) shows the given label information, where each of the given references are described in [Table 43](#).

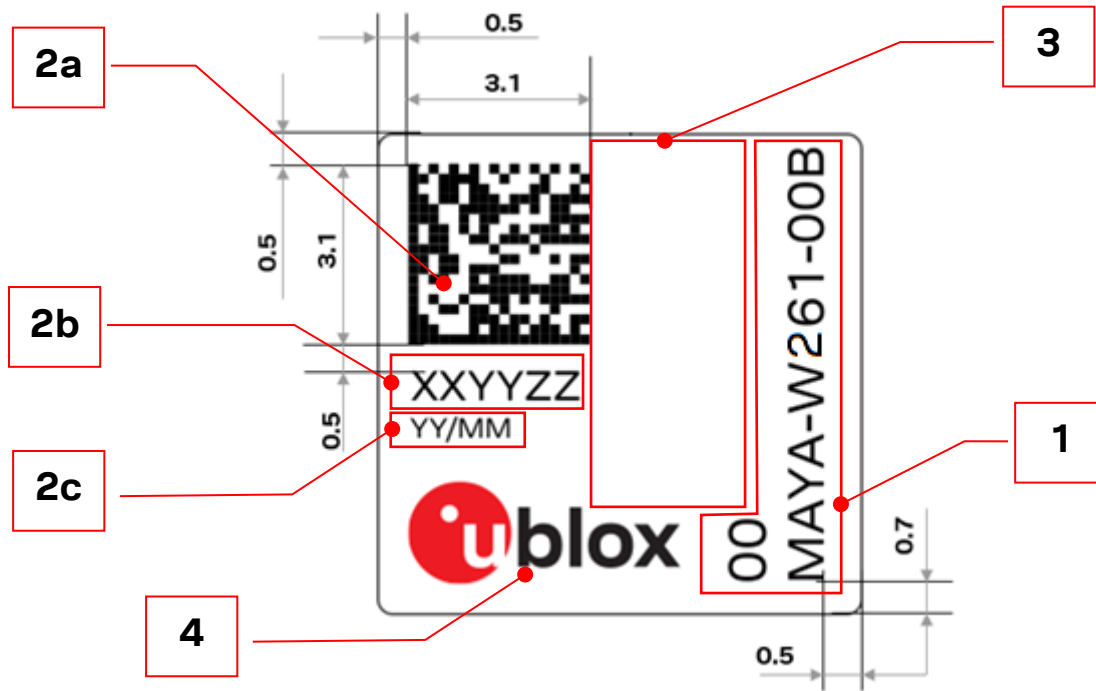


Figure 25: Label information shown on the MAYA-W2 series modules

Reference	Description
1	Text box containing product name (MODEL ID) and version
2a	Data Matrix with unique serial number of 19 alphanumeric symbols: - The first 3 symbols are used for production tracking and are an abbreviated representation of the Type number that is unique to each module variant. - The following 12 symbols represent the unique hexadecimal Bluetooth address of the module AABCCDDEEFF. See also MAC addresses. - The last 4 symbols represent the hardware and firmware version encoded HHFF.
2b	The six last hex symbols of the MAC address (AABCCDDEEFF)
2c	Date of production in the format YY/WW (year/week)
3	Placeholder for certification IDs
4	u-blox logo, where the red dot indicates the position of pin 1

Table 43: MAYA-W2 series label references

9.2 Explanation of codes

Table 44 describes the three product identifiers, namely the Type number, Model name and Ordering code.

Format	Description	Nomenclature
Product name	Describes the form factor, platform technology and platform variant. Used mostly in product documentation like this data sheet, the model name represents the most common identity for all u-blox products.	PPPP-TGVV
Ordering code	Comprises the model name – with additional identifiers to describe the major product version and quality grade.	PPPP-TGVV-TTQ
Type number	Comprises the model name and ordering code – with additional identifiers that describe minor product versions.	PPPP-TGVV-TTQ-XX

Table 44: Product code formats

9.3 Identification codes

Code	Meaning	Example
PPPP	Form factor	MAYA
TG	Platform (Technology and Generation) T – Dominant technology, For example, W: Wi-Fi, B: Bluetooth® G - Generation	W2: Wi-Fi, Generation 2
VV	Variant based on the same platform; range [00...99]	60, 61, or 66
TT	Major Product Version	00: first version
Q	Quality grade A: Automotive B: Professional C: Standard	B: Professional grade
XX	Minor product version (not relevant for certification)	Default value: 00

Table 45: Part identification code

9.4 Ordering information

Ordering Code	Product
MAYA-W260-00B	MAYA-W260 Wi-Fi 6/Bluetooth 5.3 module with two U. FL connectors, 500 pcs/reel, NXP IW611
MAYA-W261-00B	MAYA-W261 Wi-Fi 6/Bluetooth 5.3 module with two antenna pins, 500 pcs/reel, NXP IW611
MAYA-W266-00B	MAYA-W266 Wi-Fi 6/Bluetooth 5.3 module with single antenna pin and embedded PCB antenna, 500 pcs/reel, NXP IW611
MAYA-W271-00B	MAYA-W271 Wi-Fi 6/Bluetooth 5.3/802.15.4 module with two antenna pins, 500 pcs/reel, NXP IW612
MAYA-W276-00B	MAYA-W276 Wi-Fi 6/Bluetooth 5.3/802.15.4 module with single antenna pin and embedded PCB antenna, 500 pcs/reel, NXP IW612
MAYA-W276-00C	MAYA-W276 Wi-Fi 6/Bluetooth 5.3/802.15.4 module with single antenna pin and embedded PCB antenna, 500 pcs/reel, NXP IW612C, standard grade

Table 46: Product ordering codes

Appendix

A Glossary

Abbreviation	Definition
ADC	Analog to digital converter
BPF	Band pass filter
CAN	Controller area network
CTS	Clear to send
DC	Direct current
DSR	Data set ready
DTR	Data terminal ready
EIRP	Effective isotropic radiated power
GND	Ground
GPIO	General purpose input/output
H	High
I	Input (means that this is an input port of the module)
IEEE	Institute of Electrical and Electronics Engineers
I2C	Inter-integrated circuit
L	Low
LPO	Low power oscillator
MIMO	Multi-input multi-output
MSD	Moisture sensitive device
N/A	Not applicable
O	Output (means that this is an output port of the module)
PCN/IN	Product change notification / Information note
PD	Pull-down
PU	Pull-up
RMII	Reduced media independent interface
RTS	Request to send
RXD	Receive data
SDIO	Secure digital input output
SPI	Serial peripheral interface
TXD	Transmit data
UART	Universal asynchronous Receiver/Transmitter
USB	Universal serial bus

Table 47: Explanation of the abbreviations and terms used

Related documentation

- [1] Package information reference guide, [UBX-14001652](#)
- [2] MAYA-W2 system integration manual, [UBX-22011848](#)
- [3] MAYA-W2 product summary, [UBX-21047385](#)

 For product change notifications and regular updates of u-blox documentation, register on our website, www.u-blox.com.

Revision history

Revision	Date	Name	Comments
R01	02-May-2022	bcur	Initial release
R02	20-May-2022	bcur	Power down pin specification table added in Power down section.
R03	20-May-2022	lfar	Revised references to regulatory compliance information previously envisaged as a separate application note but now included in the system integration manual. Updated Contact information boilerplate.
R04	05-Jul-2022	lfar	Updated to include the new modules variant MAYA-W276.
R05	18-Jul-2023	lfar	Document updated for release of Engineering samples: Included minor updates to Functional description . Added table data for typical current consumption in Bluetooth power consumption and IEEE 02.15.4 power consumption . Added typical output power and antenna performance values for single antenna module variants in Wi-Fi . Revised measured radiated power and peak gain in Antenna radiation patterns . Revised target country/regions in Qualifications and approvals . Added MAYA-W266 and MAYA-W267 block diagrams . Added Figure 9 MAYA-W260 antenna configuration (top view). Updated Reserved MAC addresses to include 802.15.4 radio. Updated contact information.
R06	26-Jan-2024	lfar, tngu, mzes	Product status updated to Initial production for MAYA-W2xx-00B variants. Added standard grade MAYA-W276-00C. Added tape and reel specification in Packaging . Changed default baud rate of the UART interface to 115200 baud. Updated Qualifications and approvals and Product labeling . Corrected internal pull-up value on PDn pin in Table 24 . Added Antenna Diversity feature in External RF antenna interface and other relevant sections.

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For further support and contact information, visit us at www.u-blox.com/support.